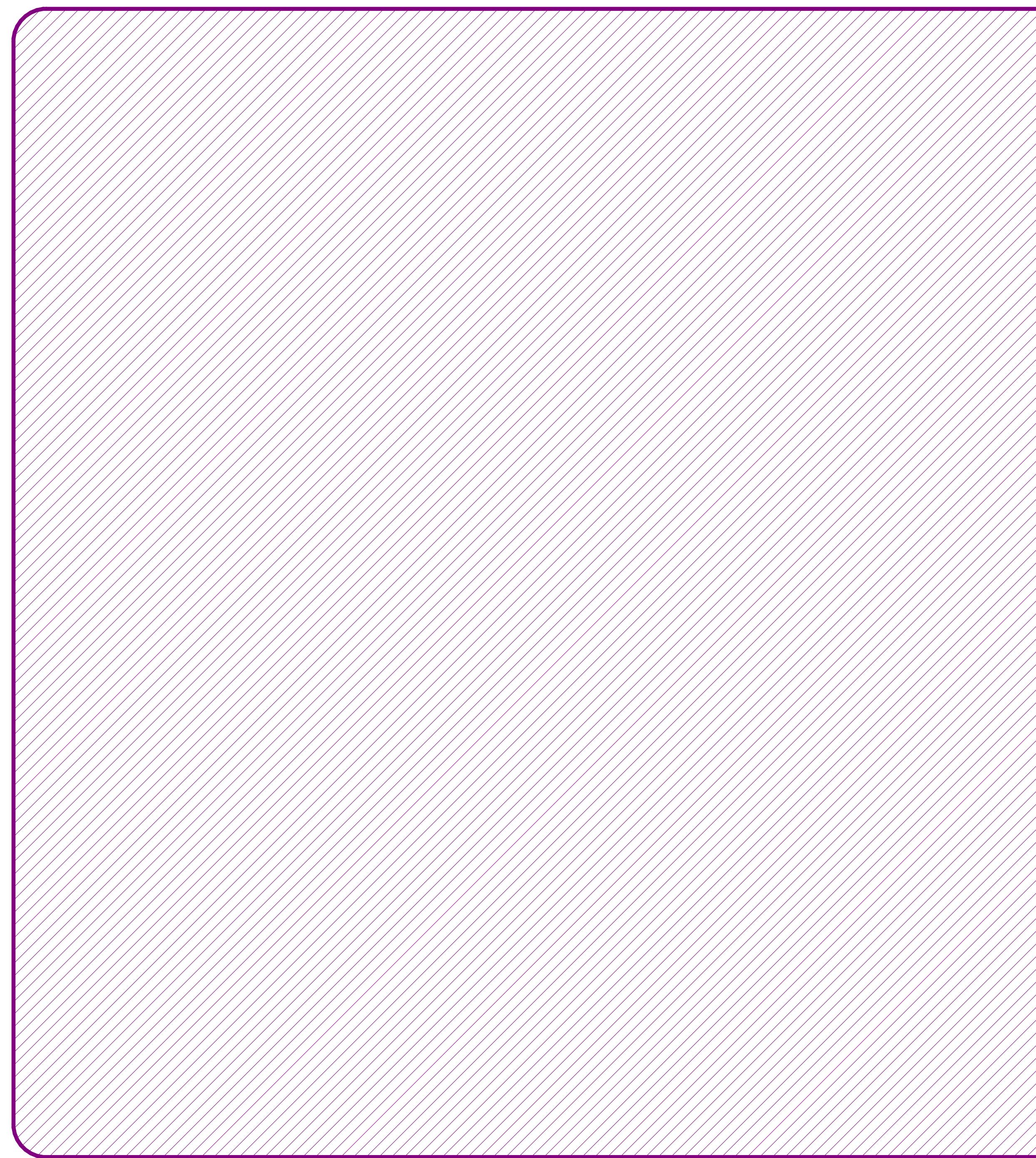
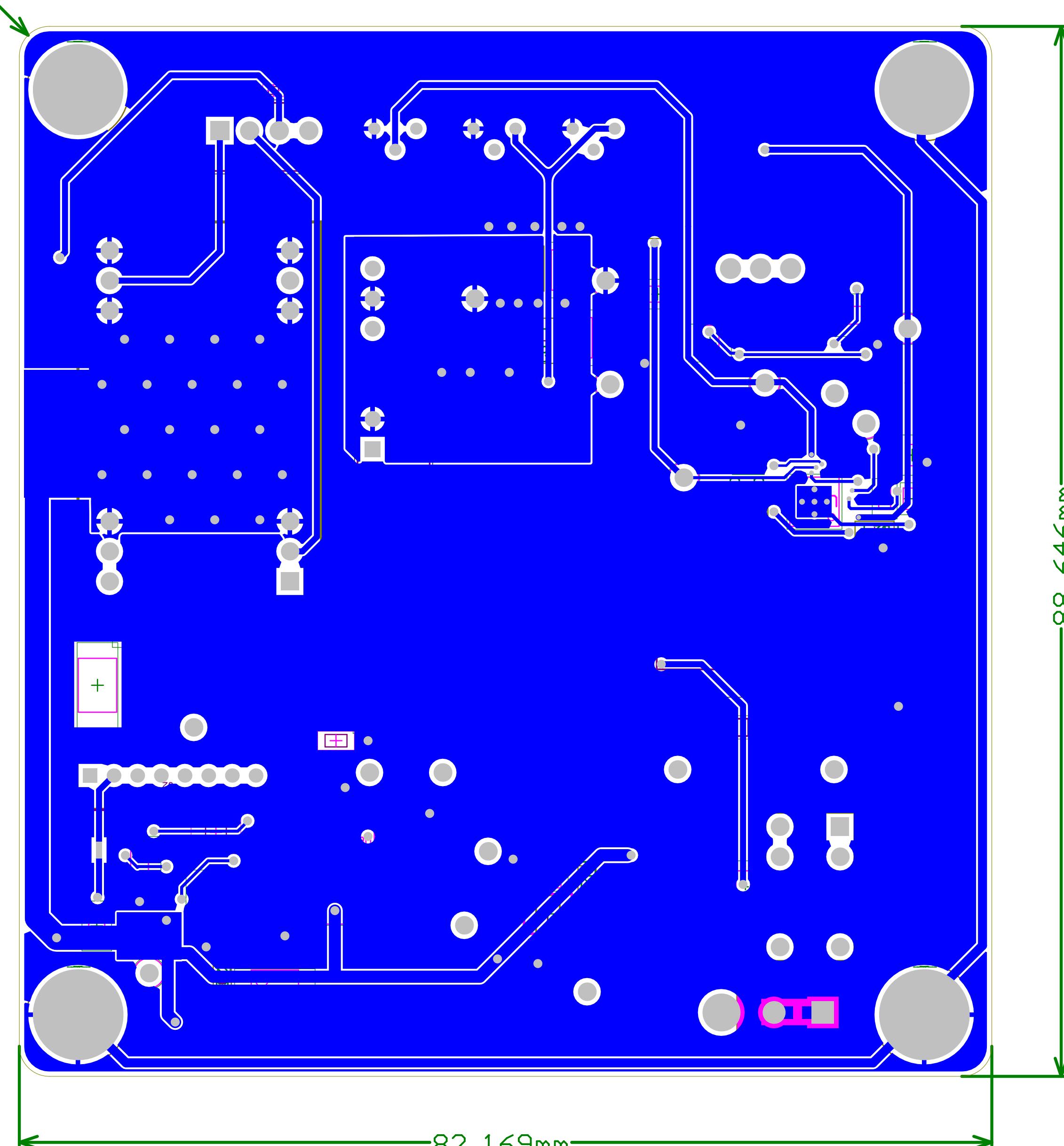


Layer	Name	Material	Thickness	Constant	Gerber	Board Layer Stack
	Top Overlay				GTO	
	Top Solder	SM-001	1.00mil	4	GTS	
1	Top Layer	Copper	1.40mil		GTL	
	Dielectric 1	FR-4	58.00mil	4.2		
2	Bottom Layer	Copper	1.40mil		GBL	
	Bottom Solder	SM-001	1.00mil	4	GBS	
	Bottom Overlay				GBO	

Total board thickness: 62.80mil

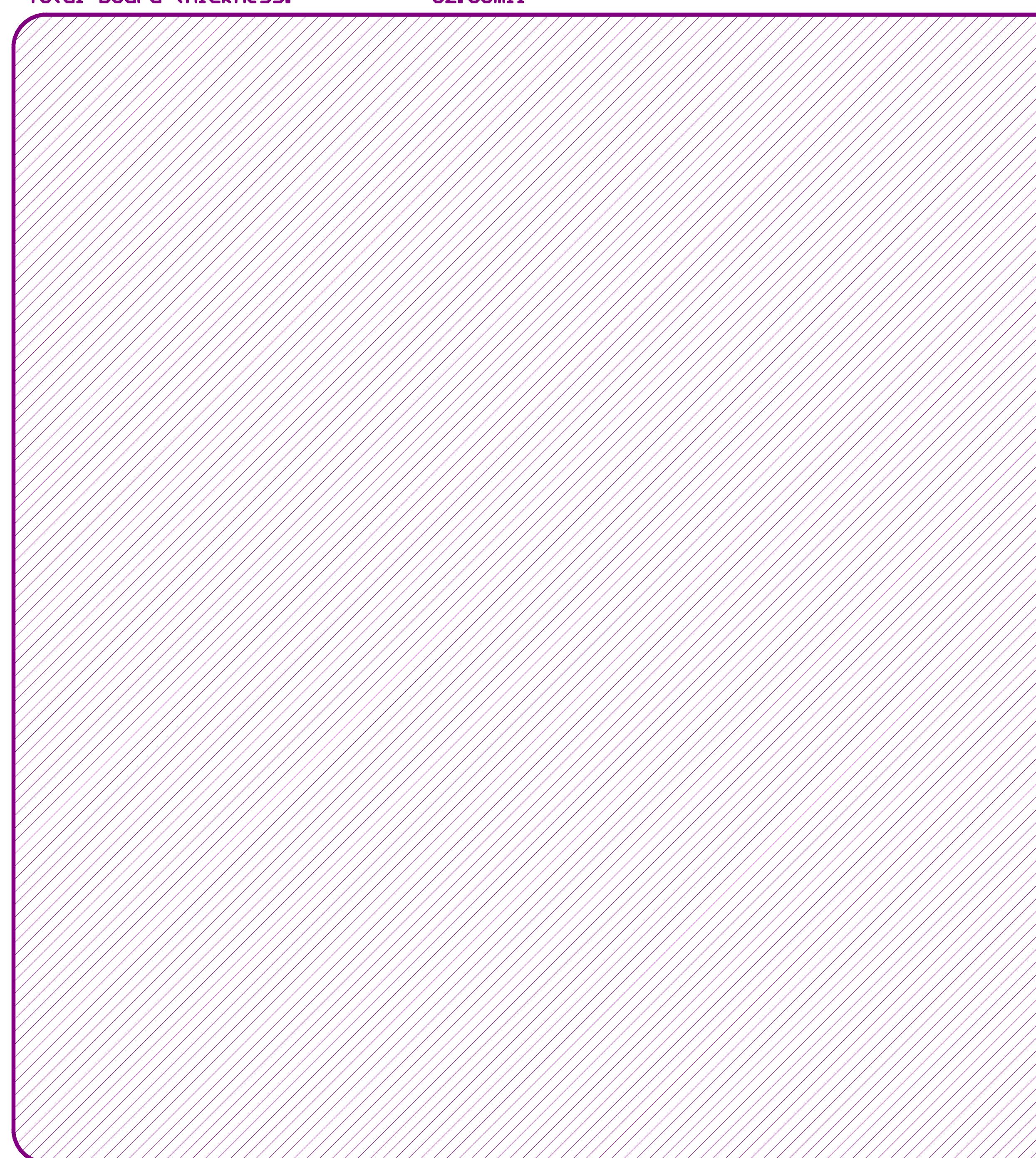


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Size: Letter	Number:
Date: 2/19/2020	Revision:
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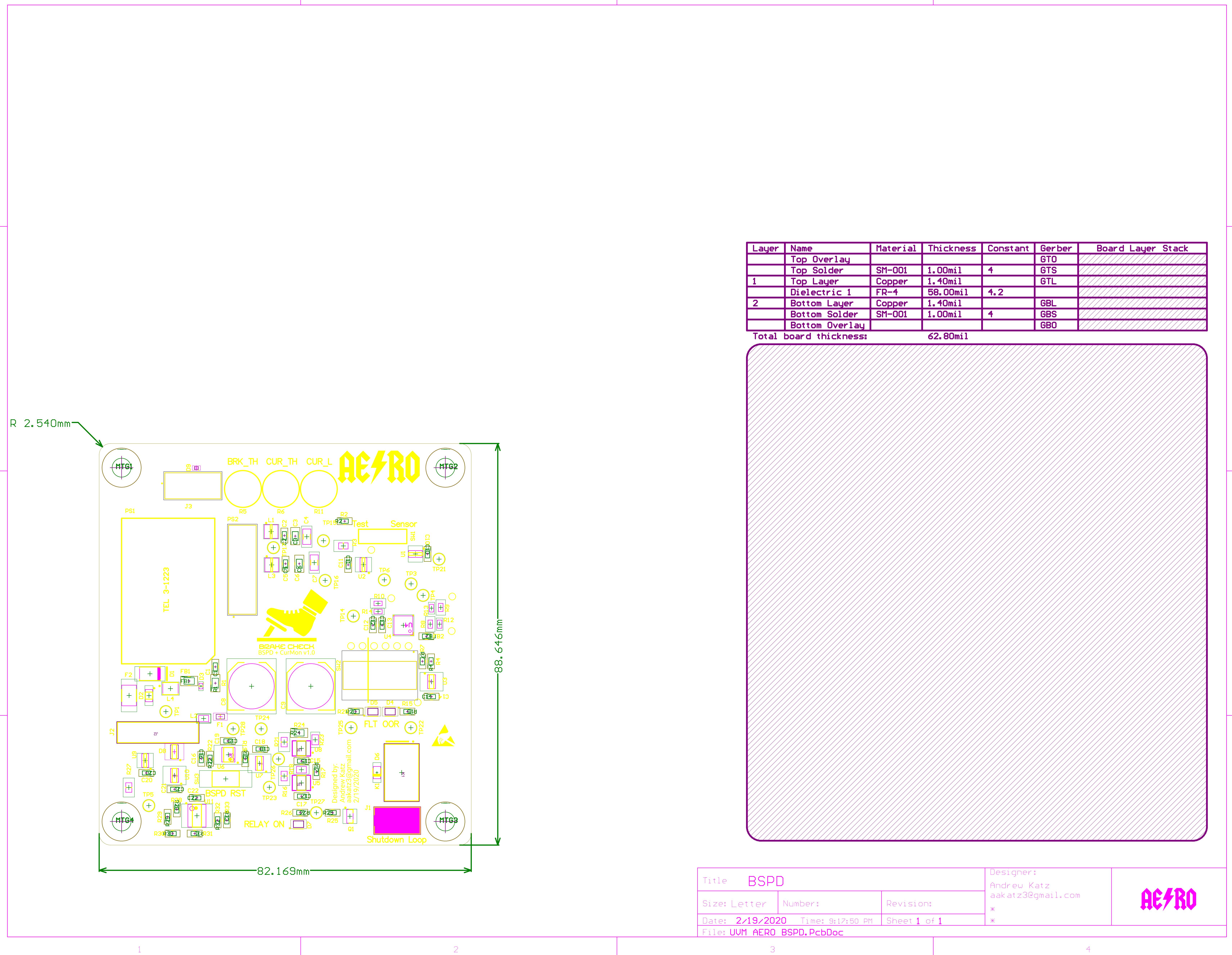


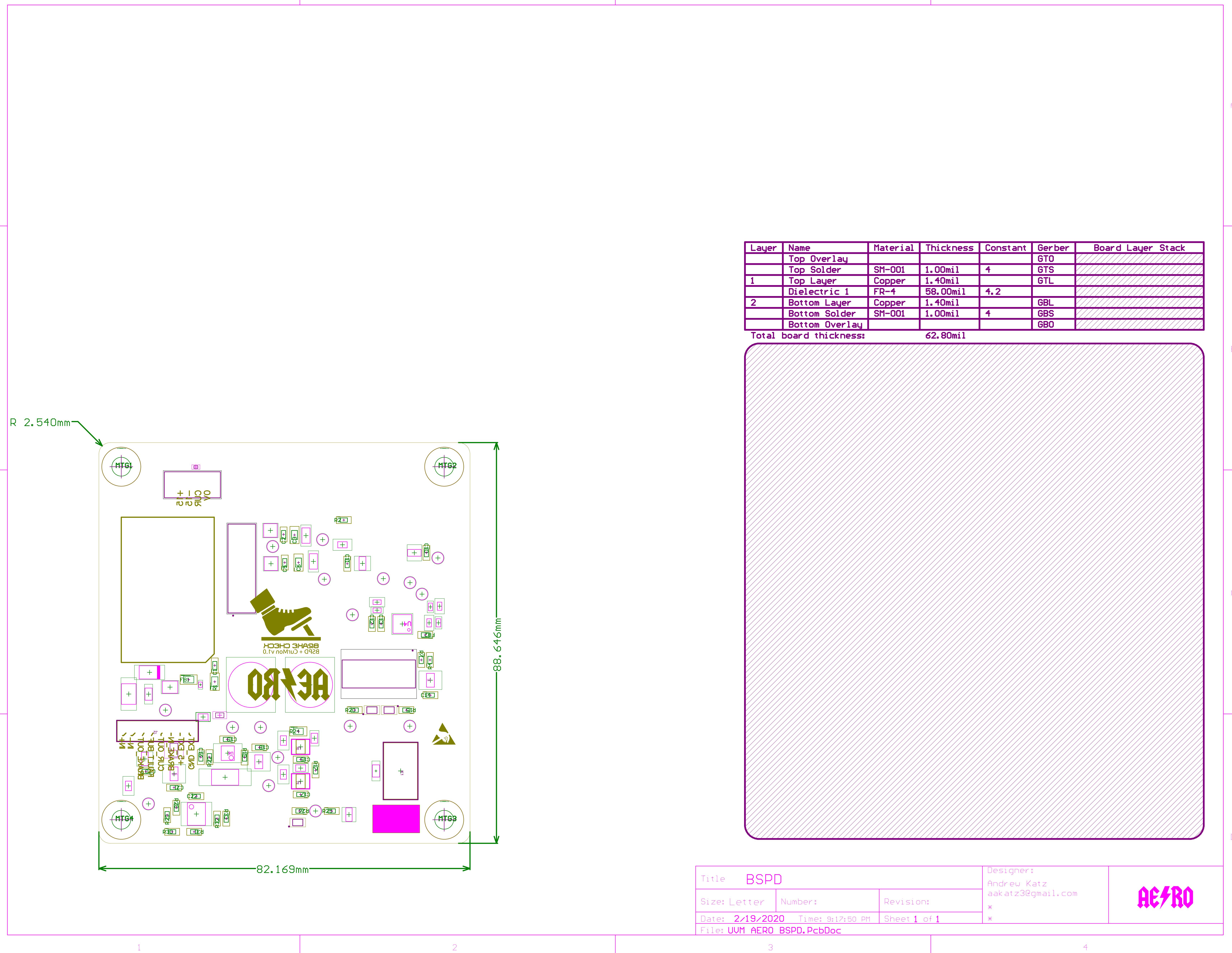
Layer	Name	Material	Thickness	Constant	Gerber	Board Layer Stack
	Top Overlay				GTO	
	Top Solder	SM-001	1.00mil	4	GTS	
1	Top Layer	Copper	1.40mil		GTL	
	Dielectric 1	FR-4	58.00mil	4.2		
2	Bottom Layer	Copper	1.40mil		GBL	
	Bottom Solder	SM-001	1.00mil	4	GBS	
	Bottom Overlay				GBO	

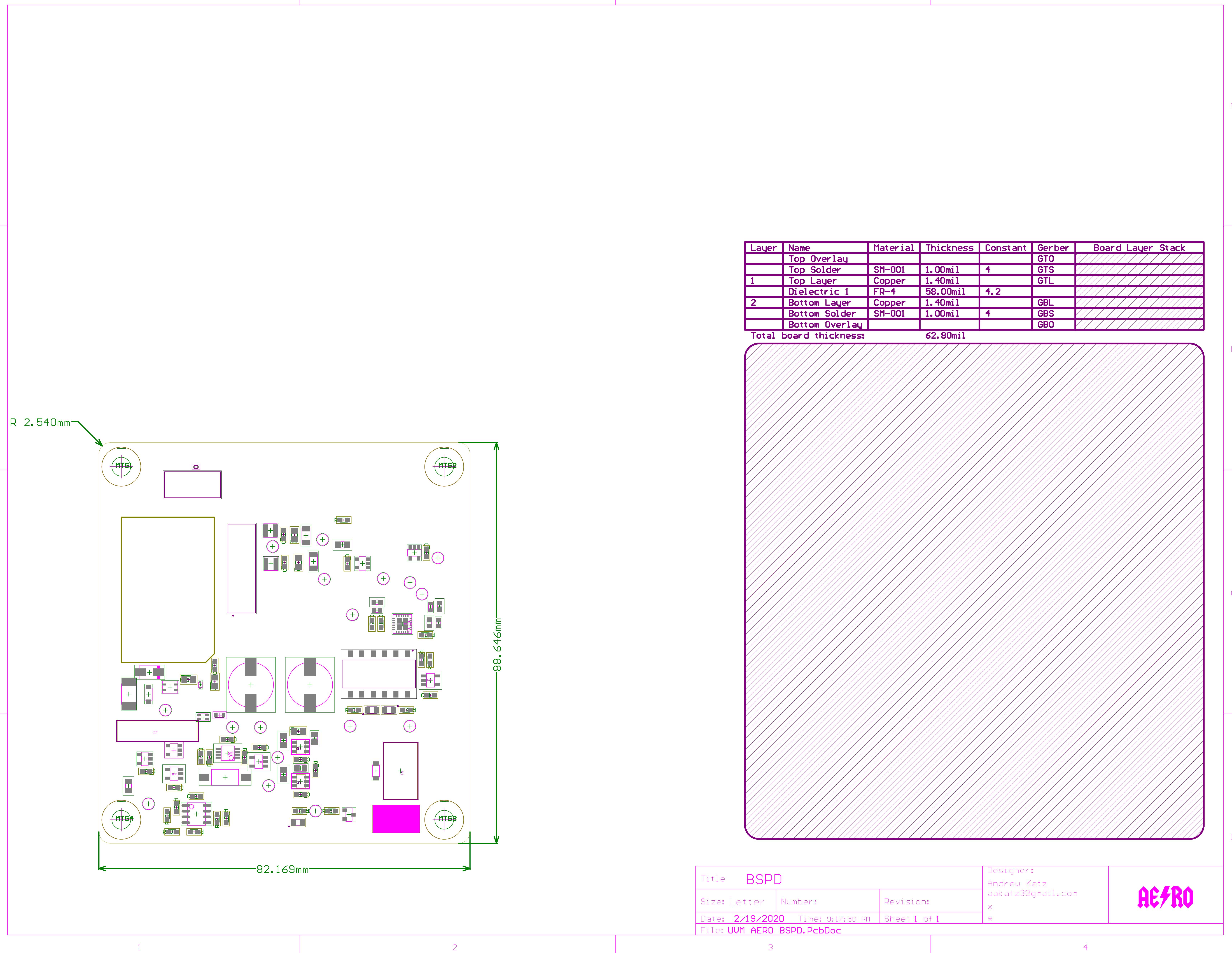
Total board thickness: 62.80mil

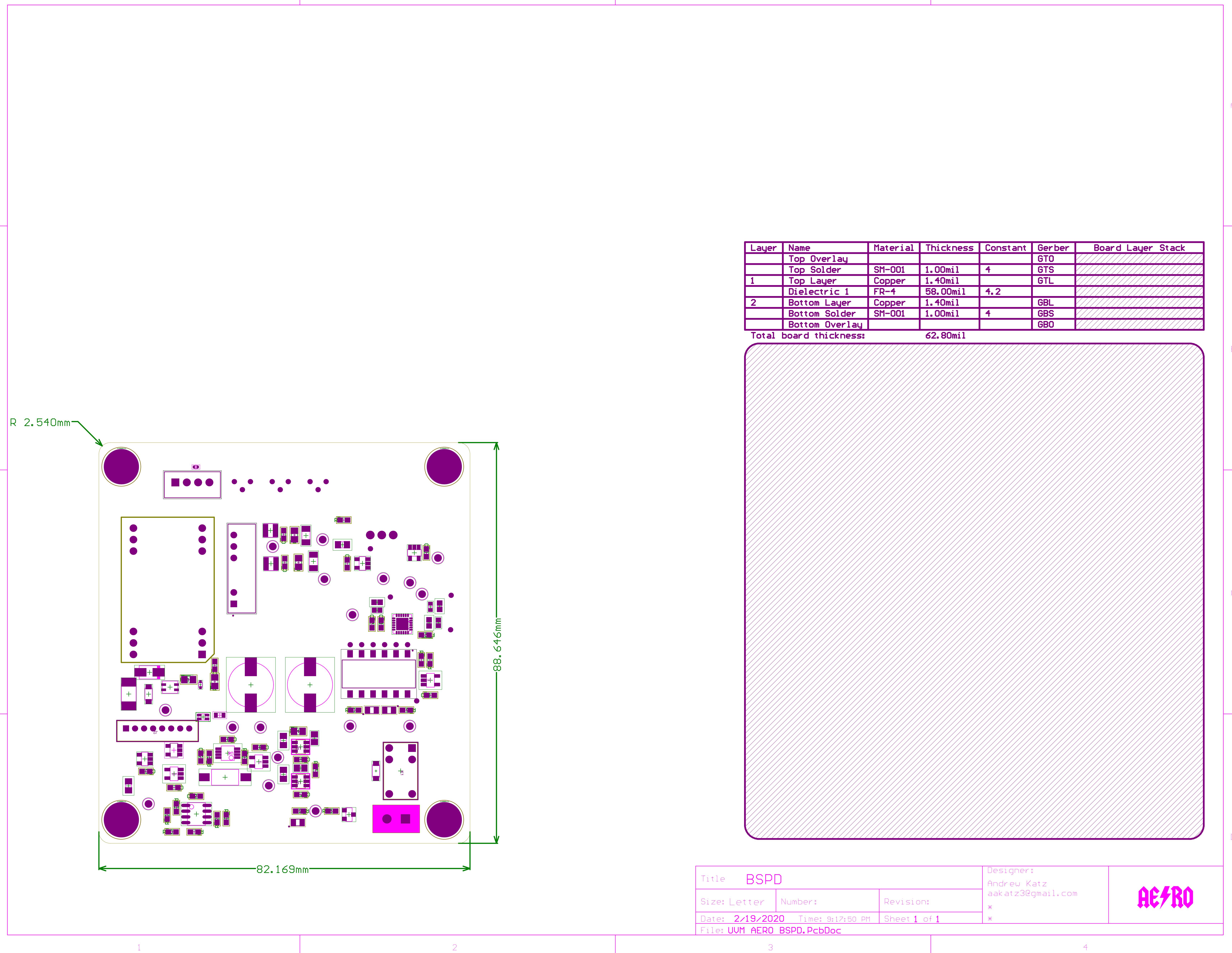


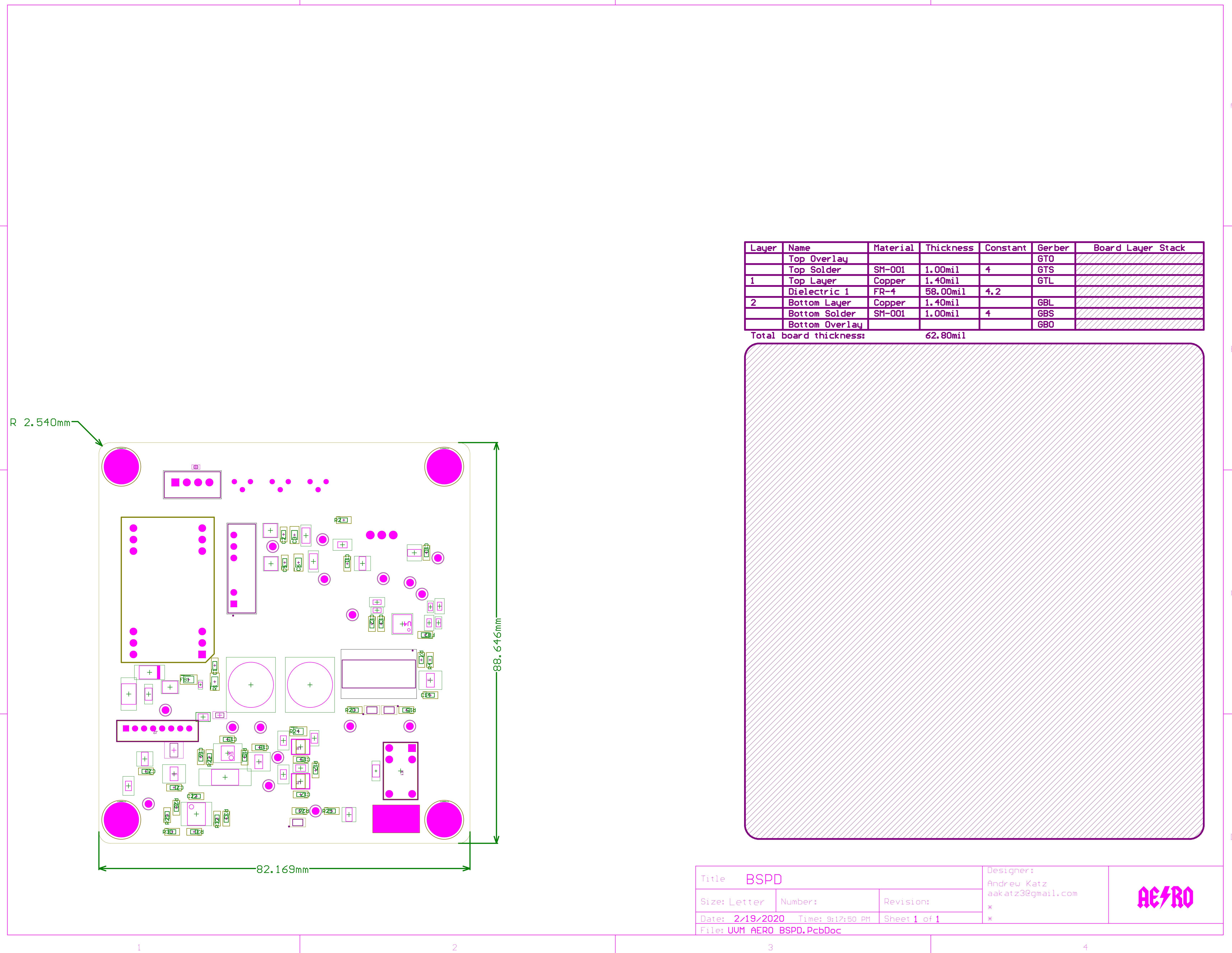
Title: BSPD	Designer: Andreu Katz aakatz3@gmail.com
Size: Letter	Number:
Date: 2/19/2020	Revision:
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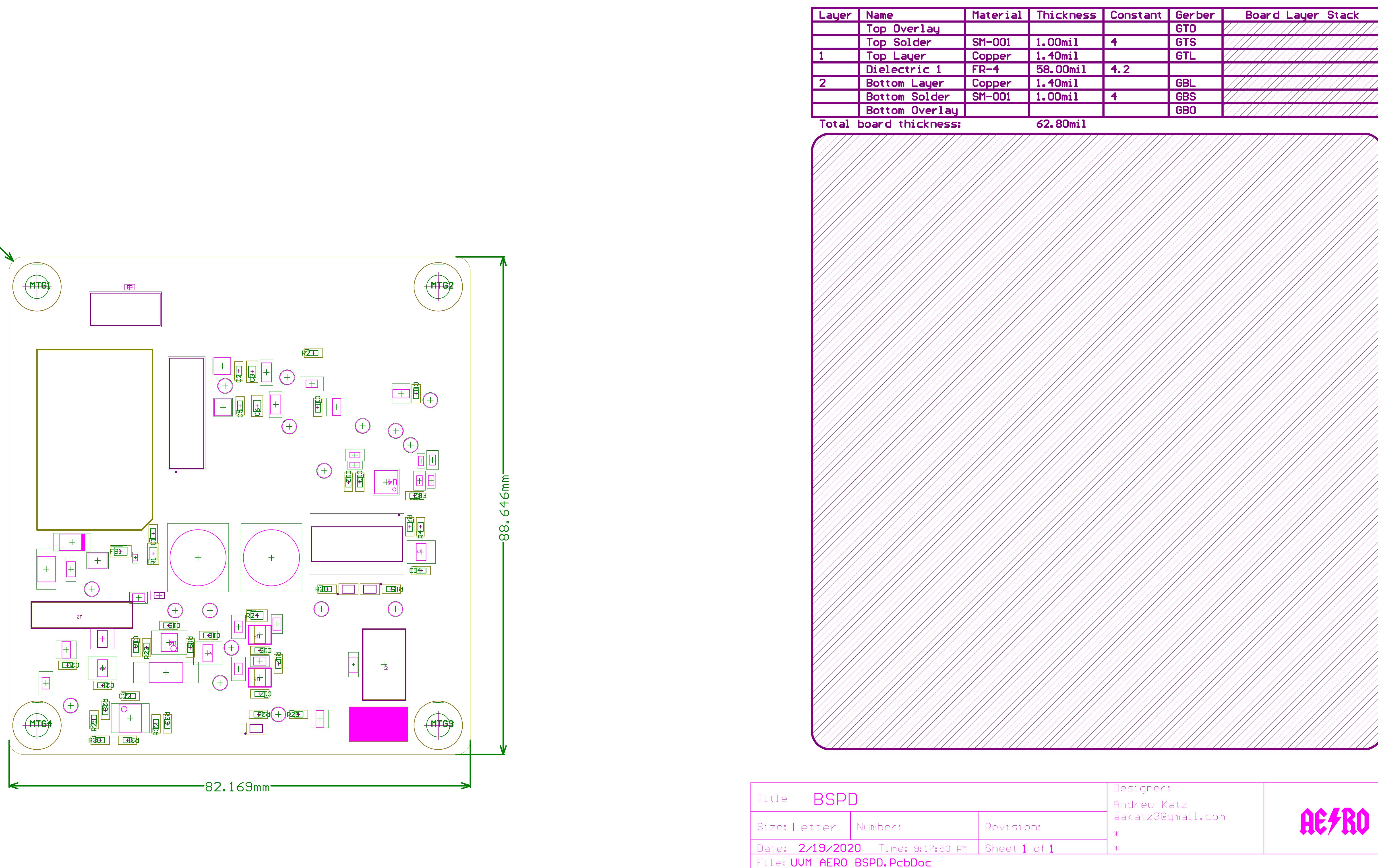


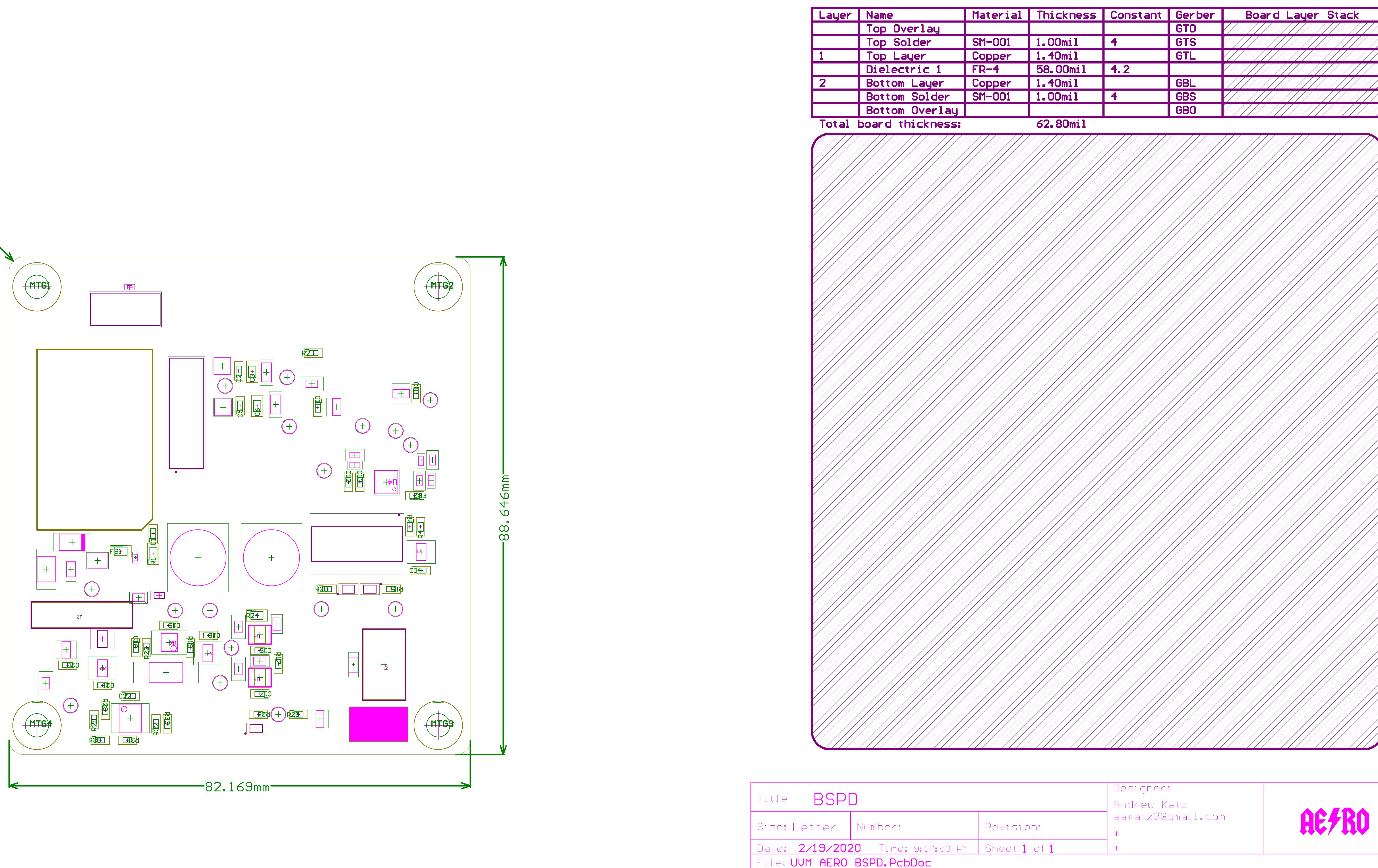


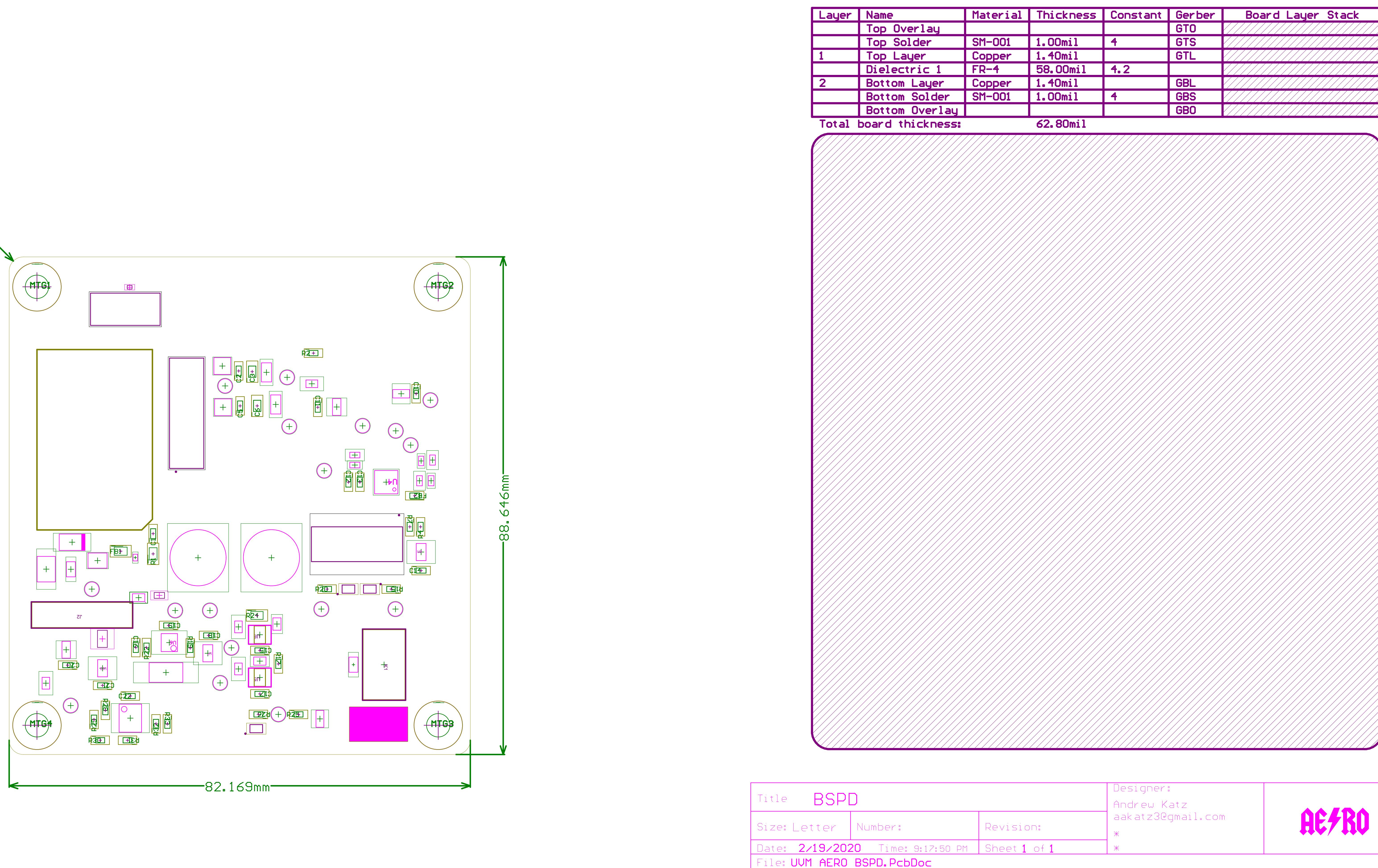


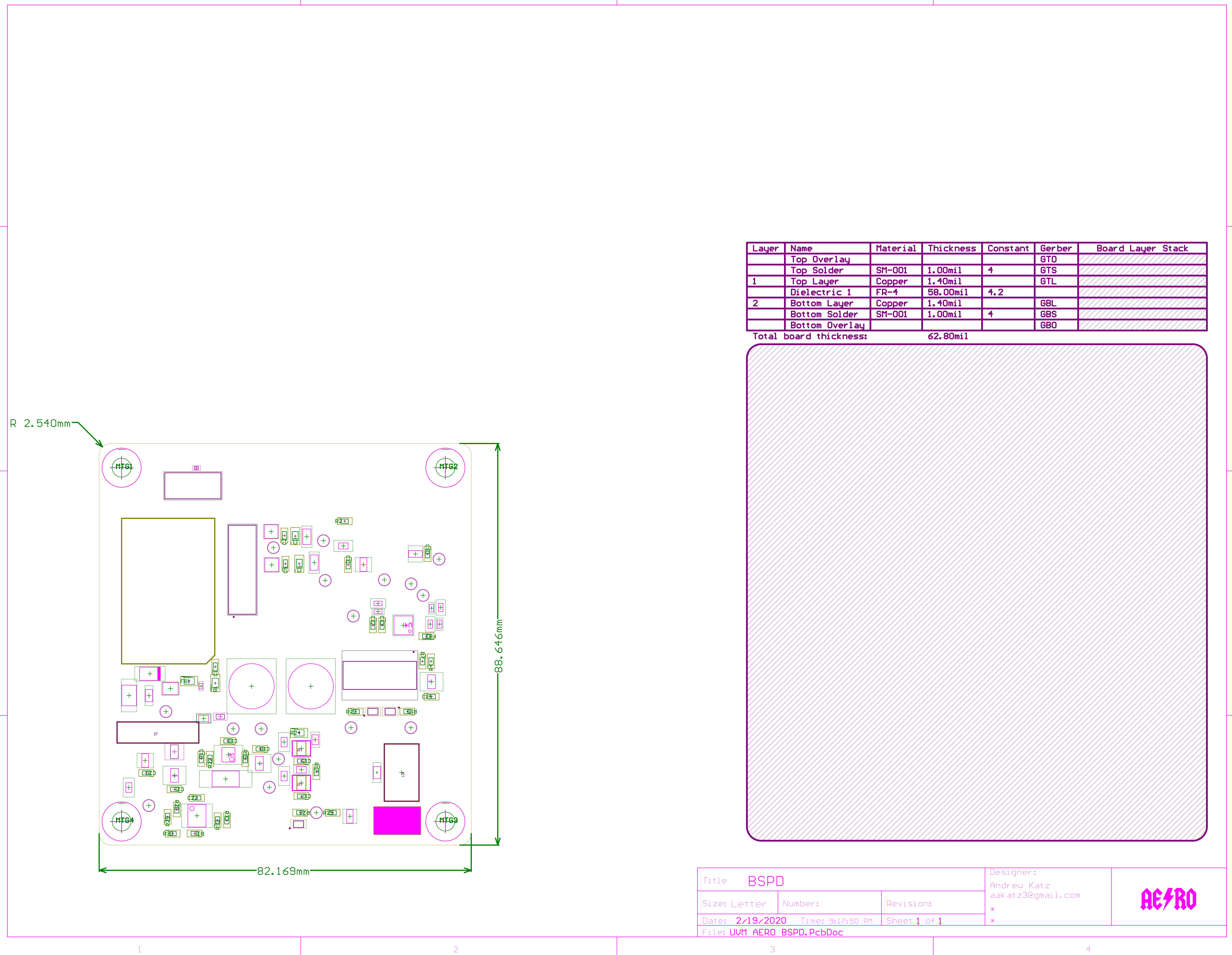


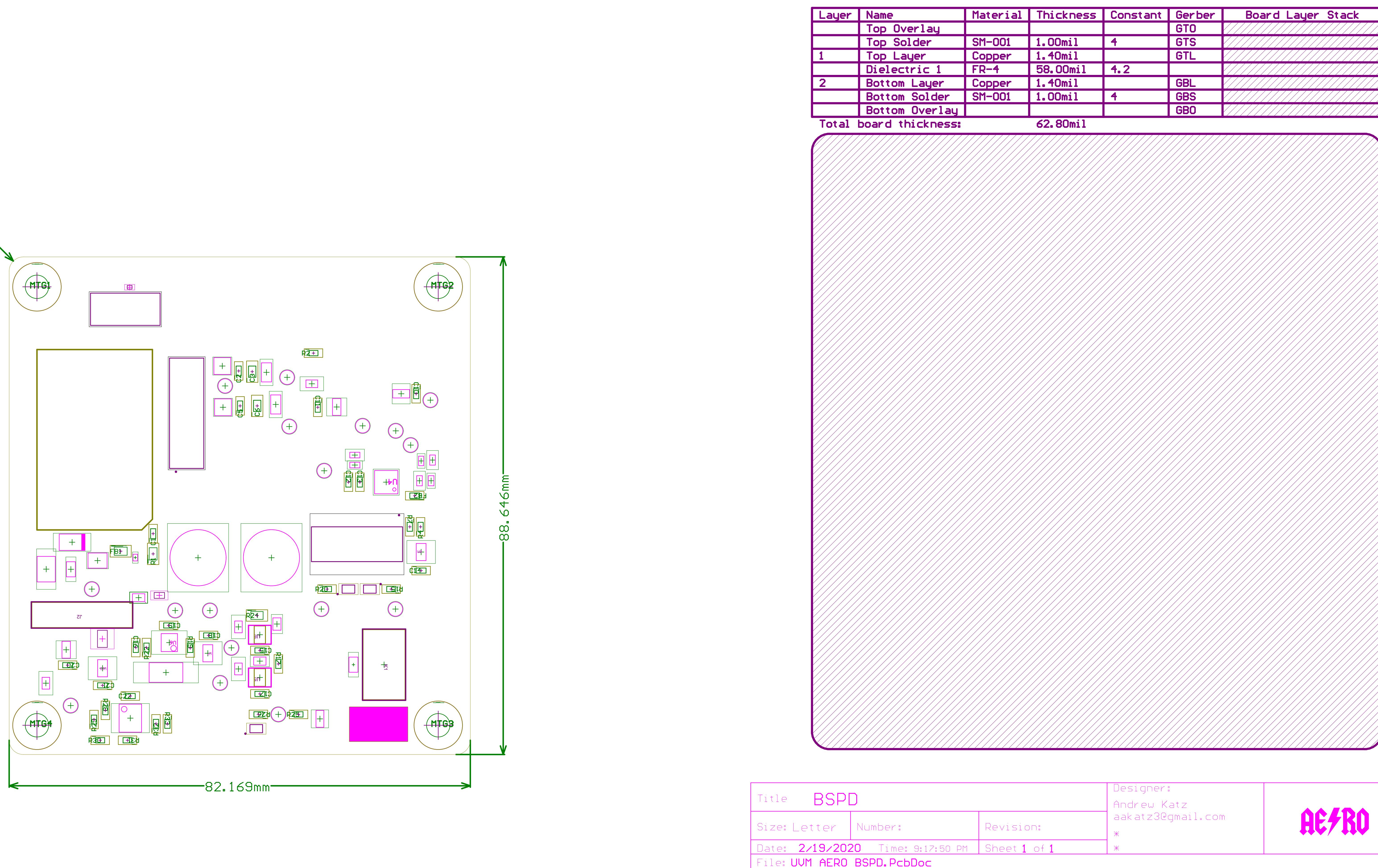


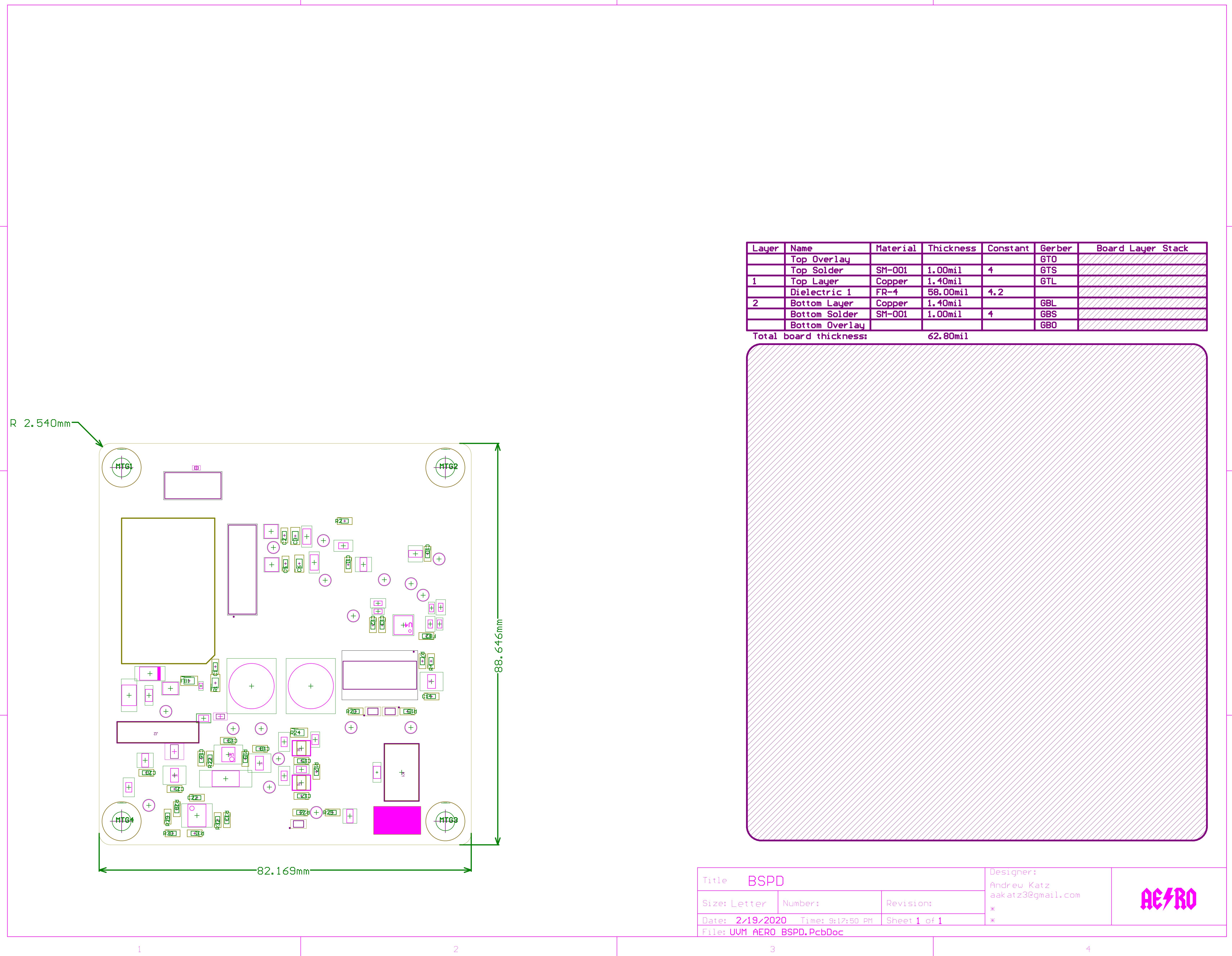




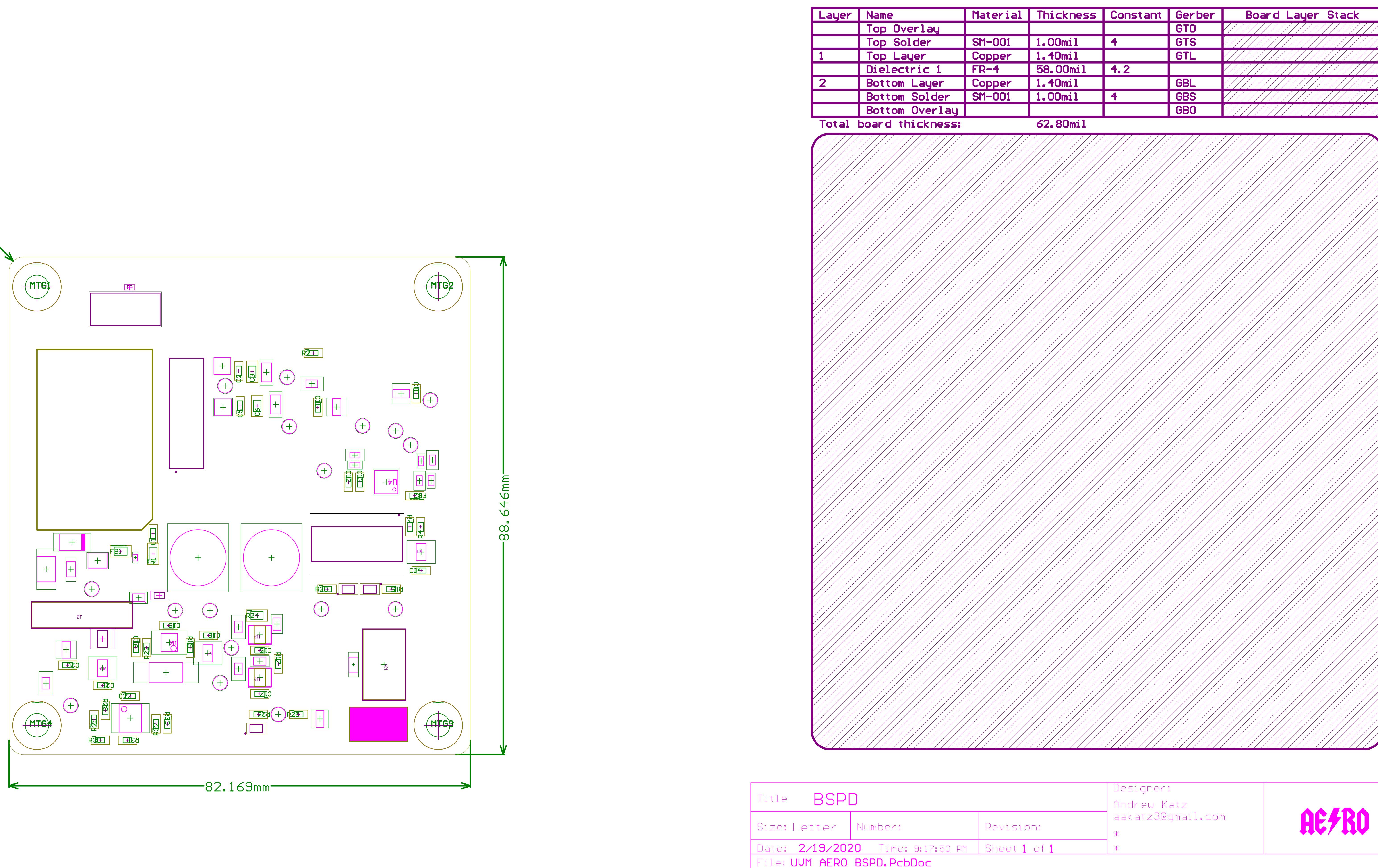


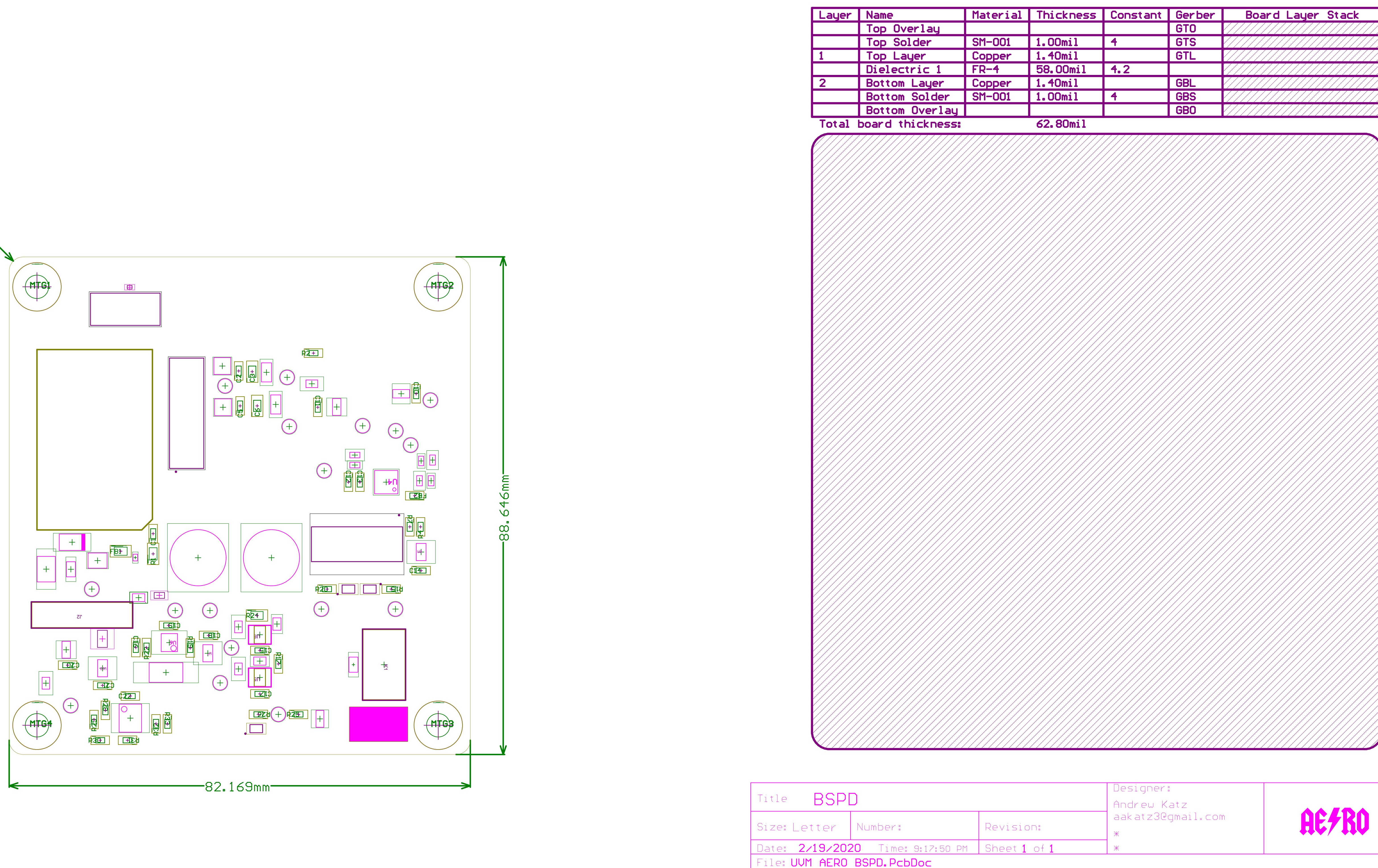


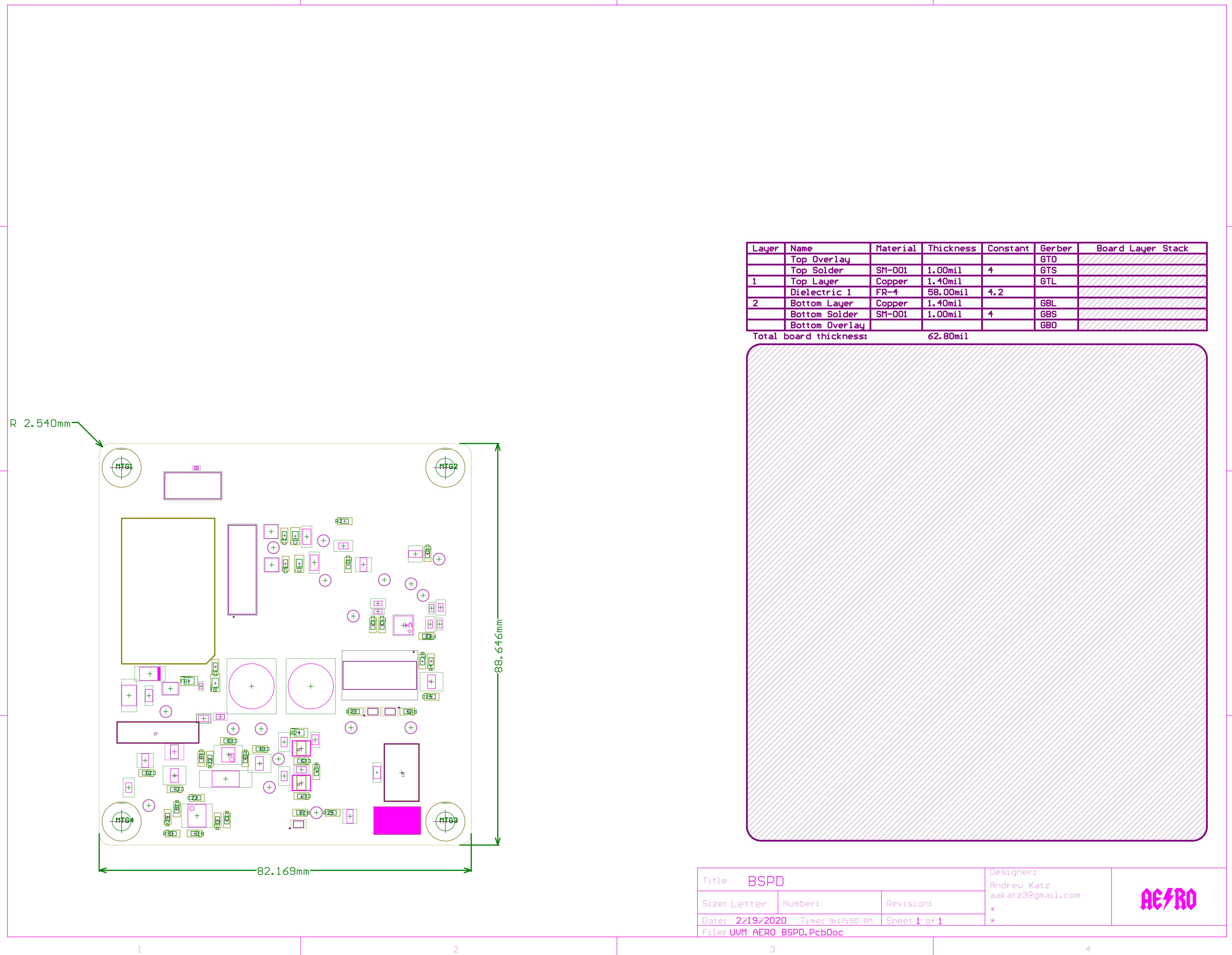


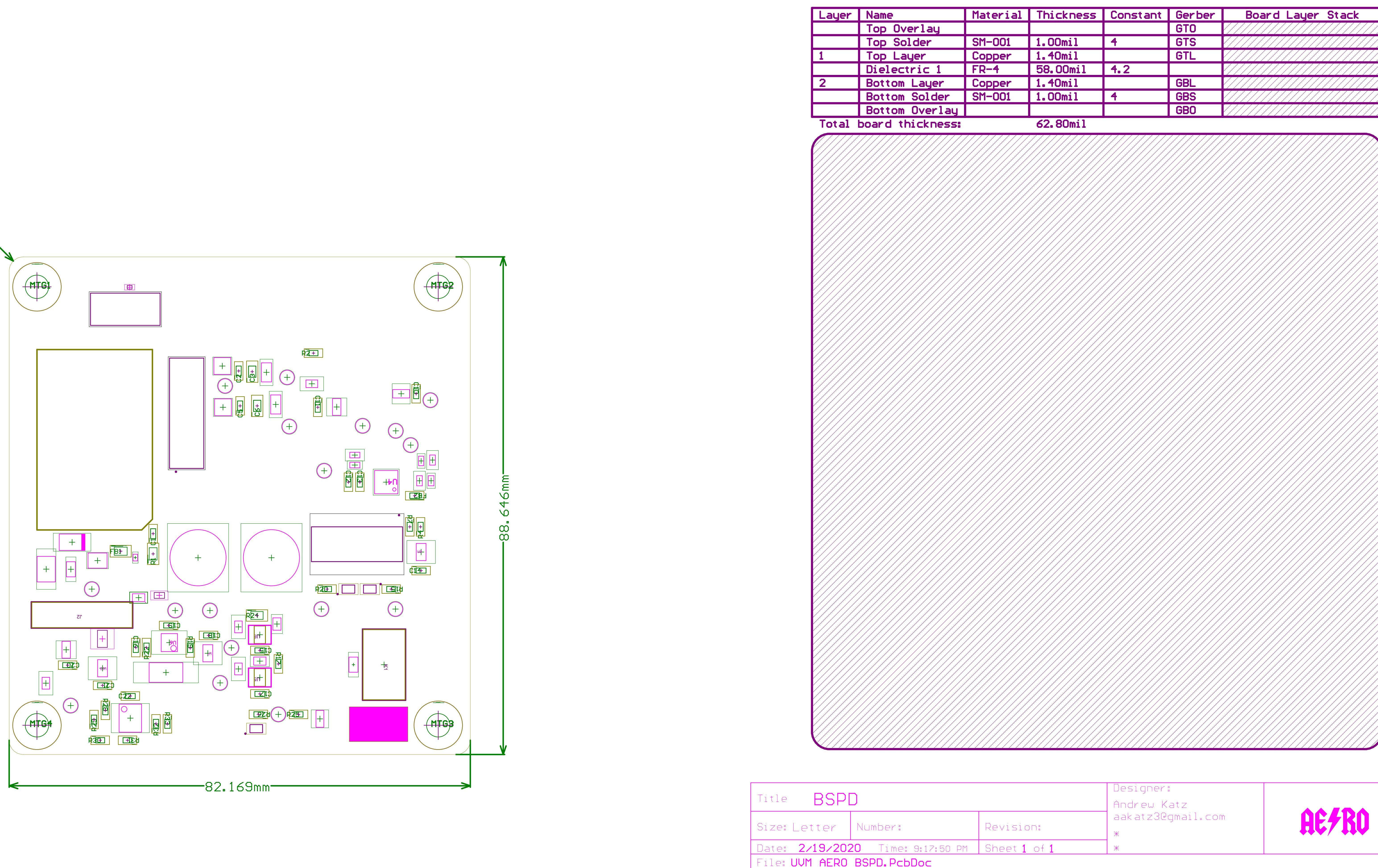


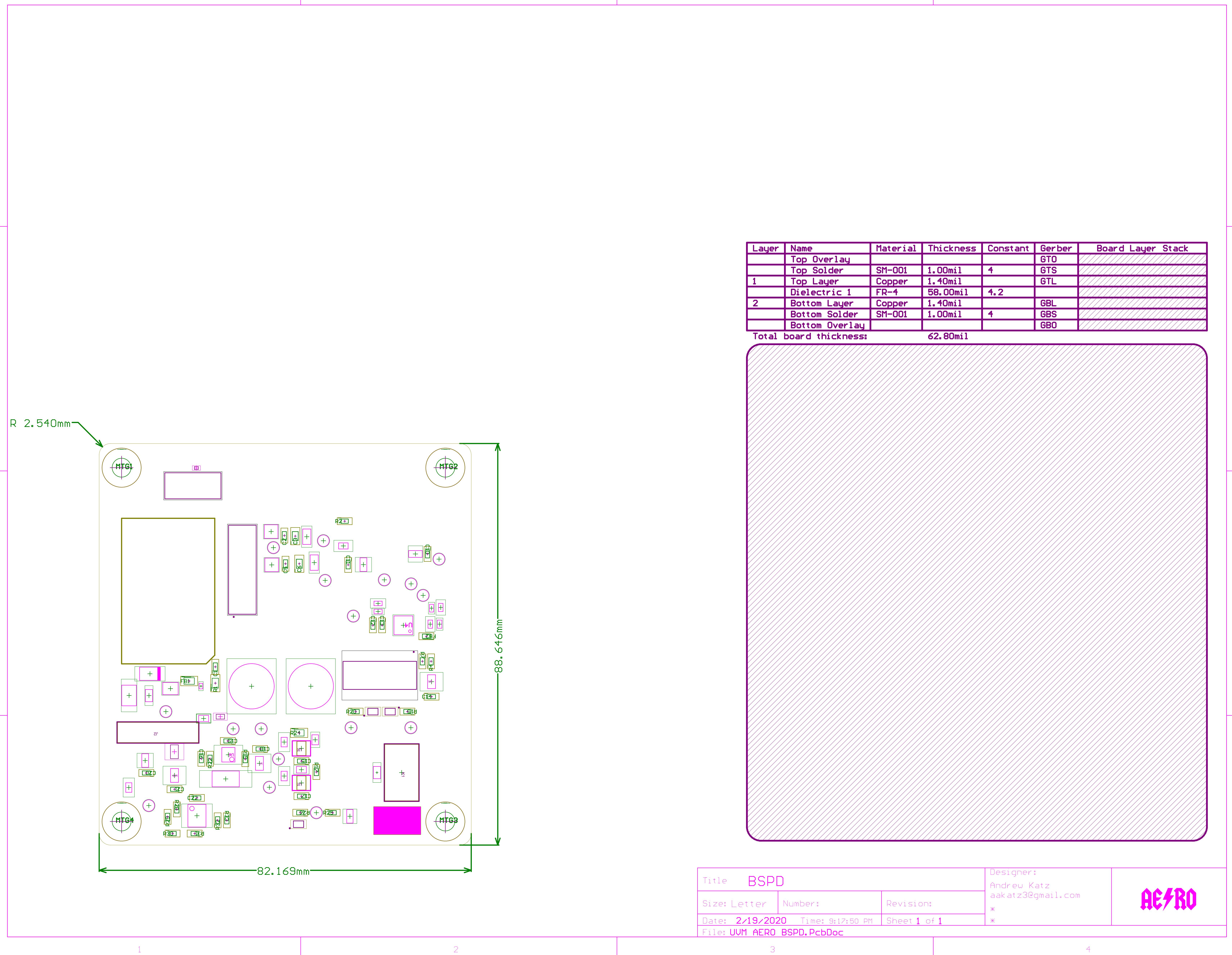
Title: <b>BSPD</b>	Designer: Andreu Katz aakatz3@gmail.com
Size: Letter	Number:
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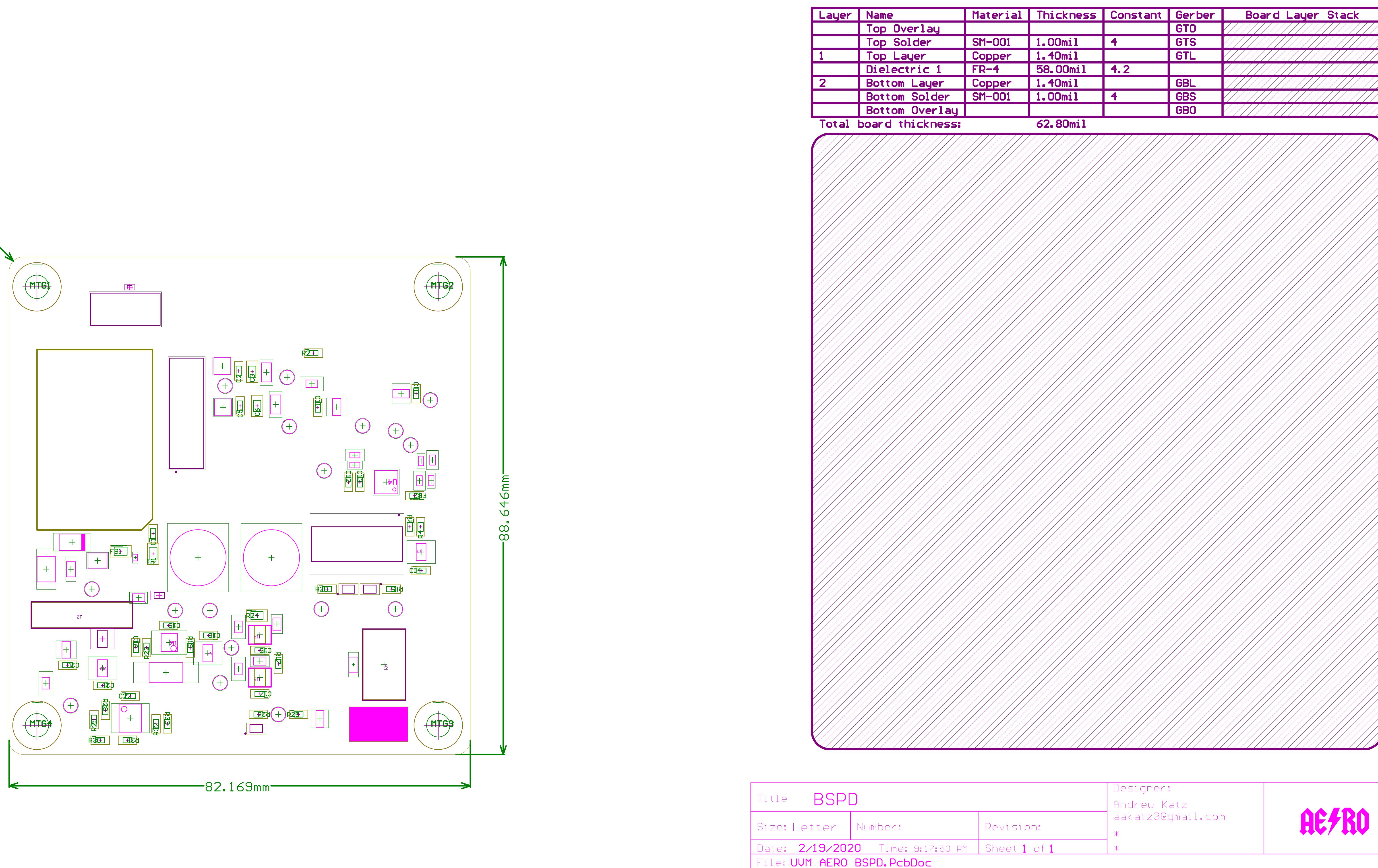


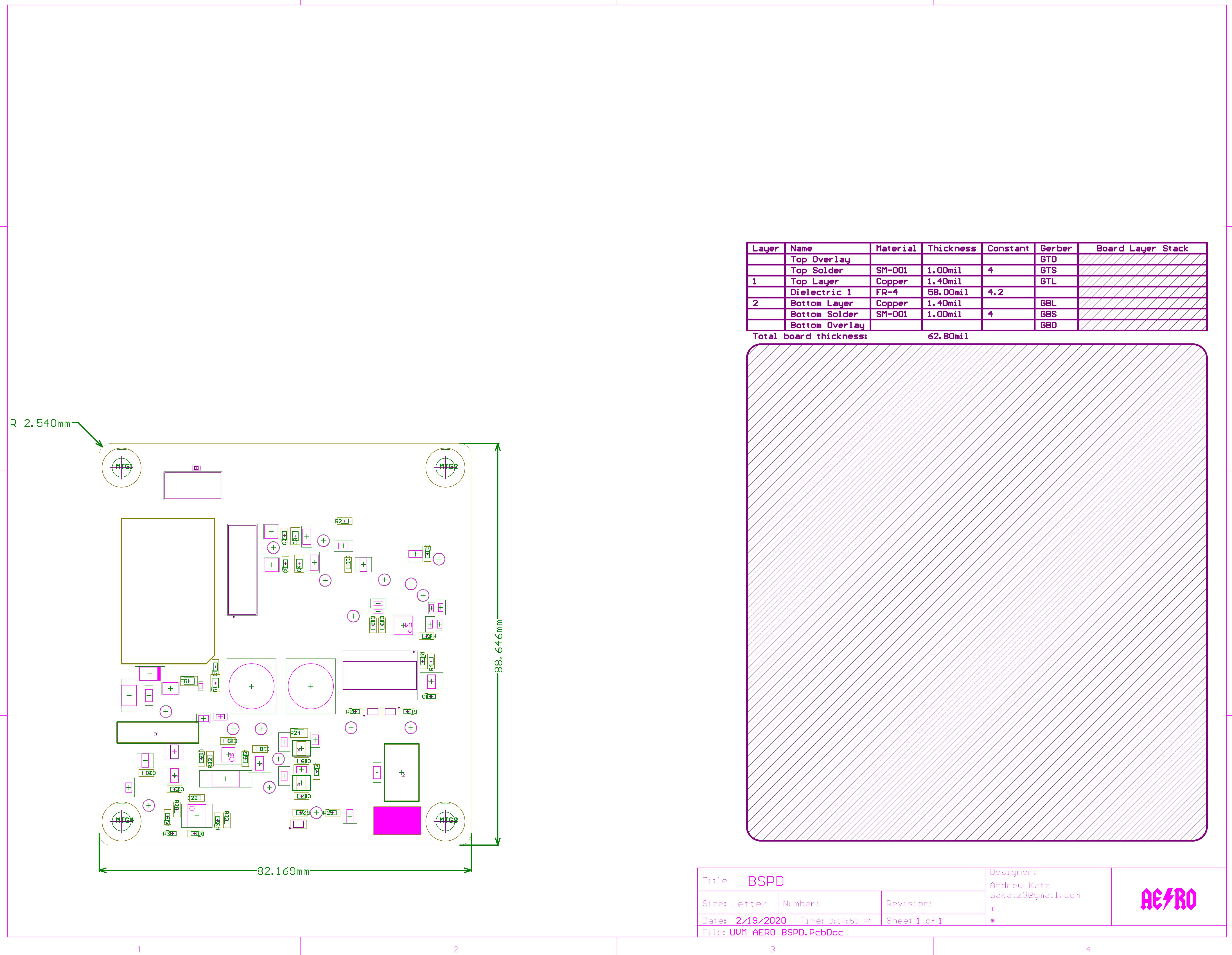


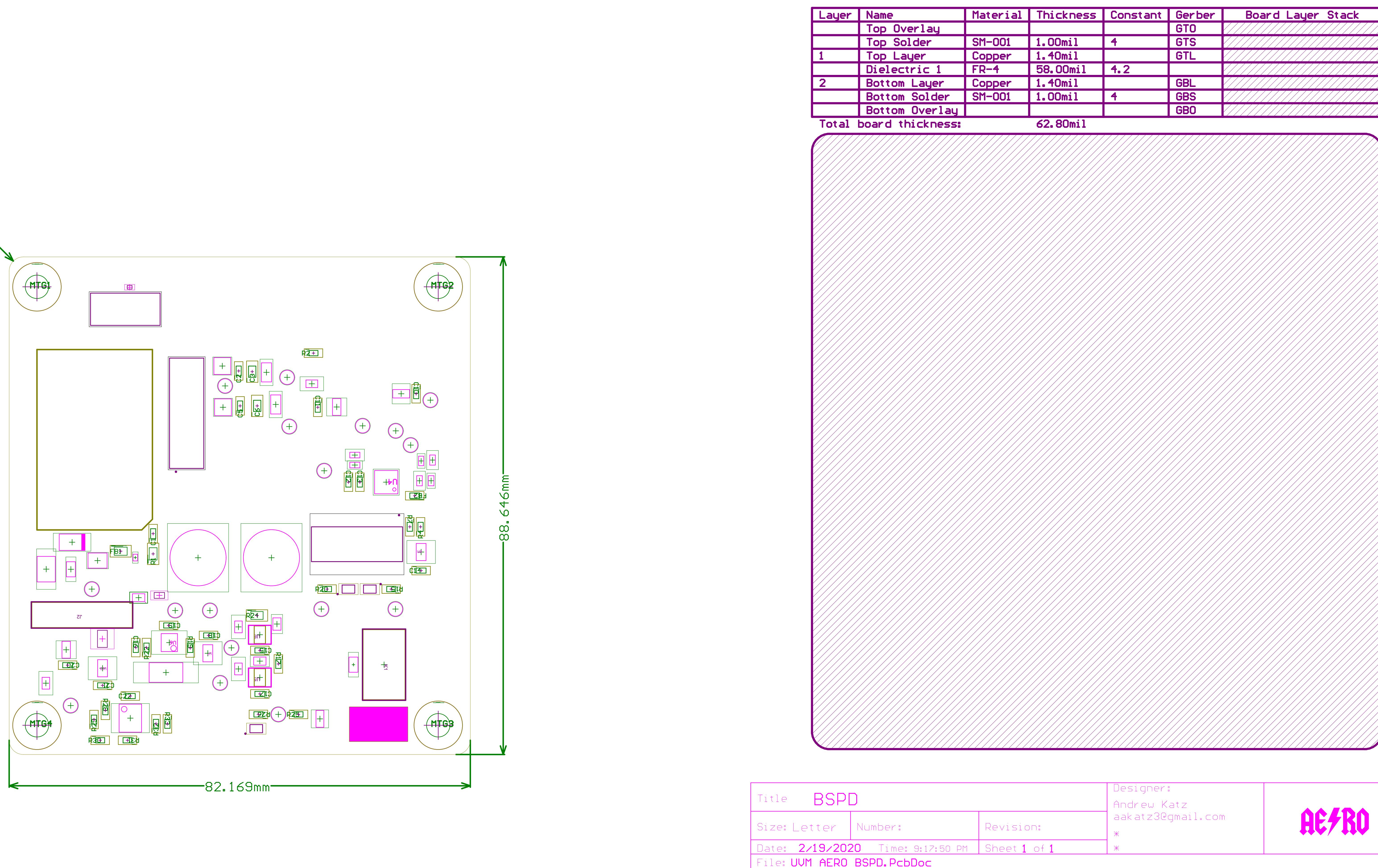


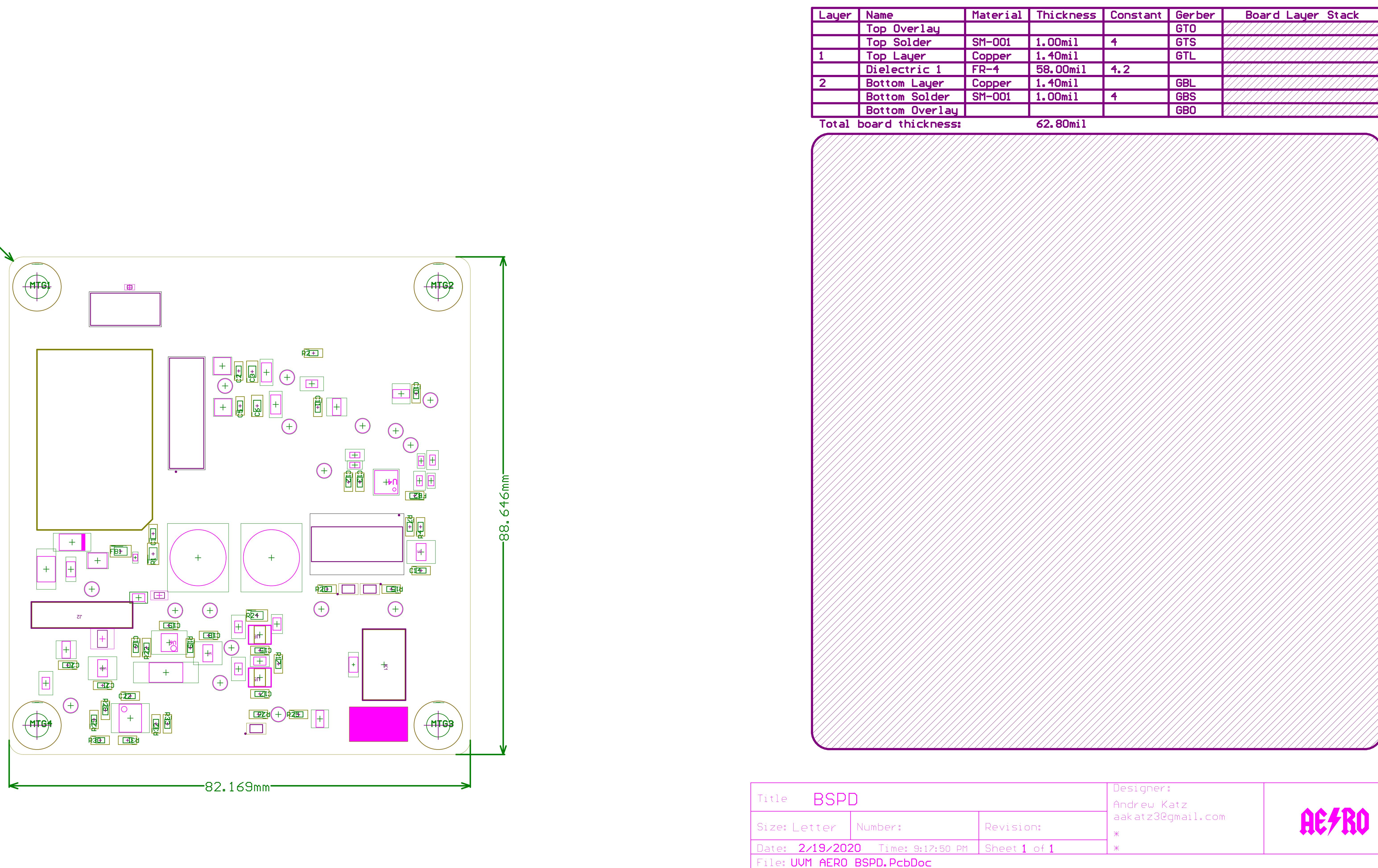


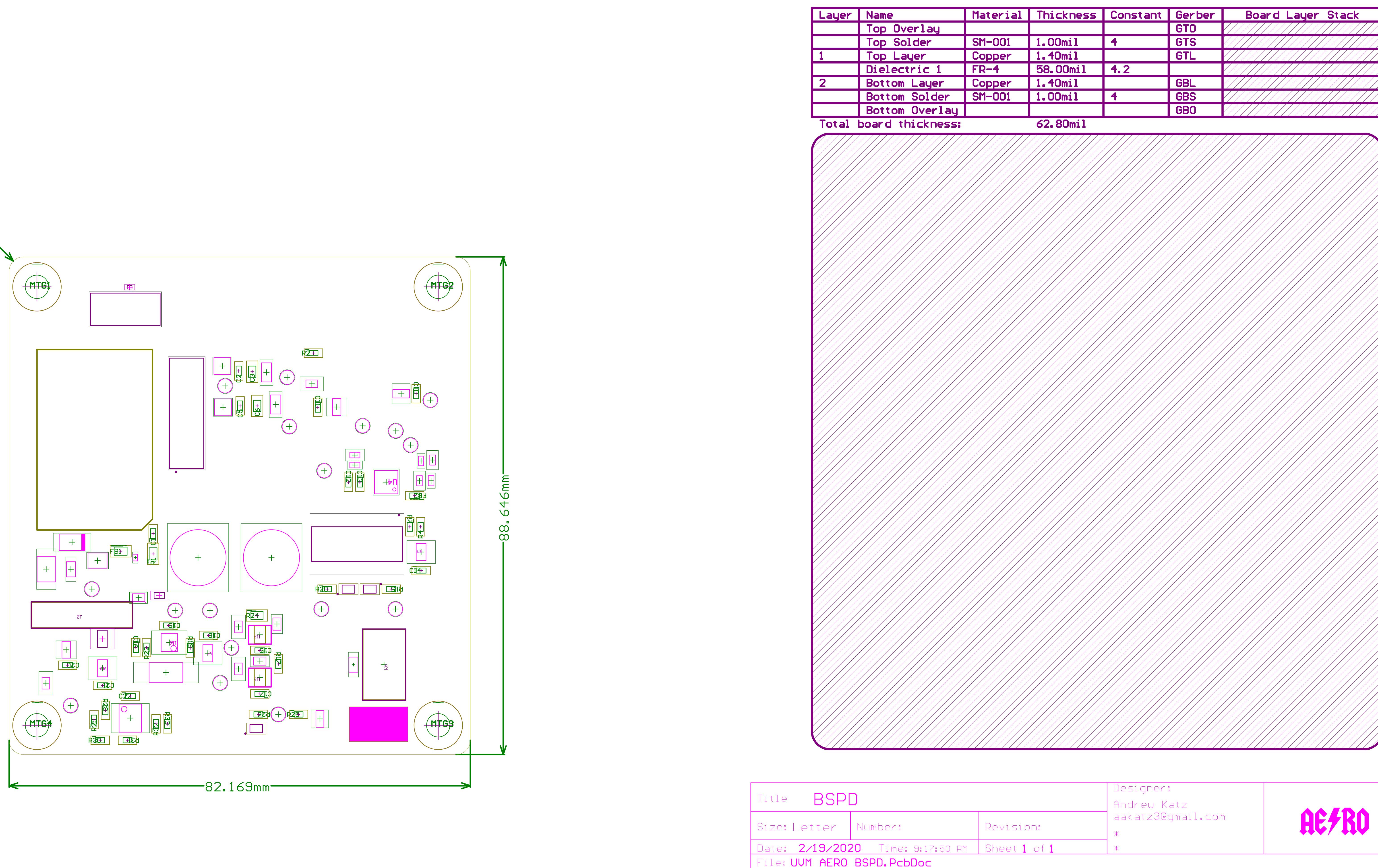


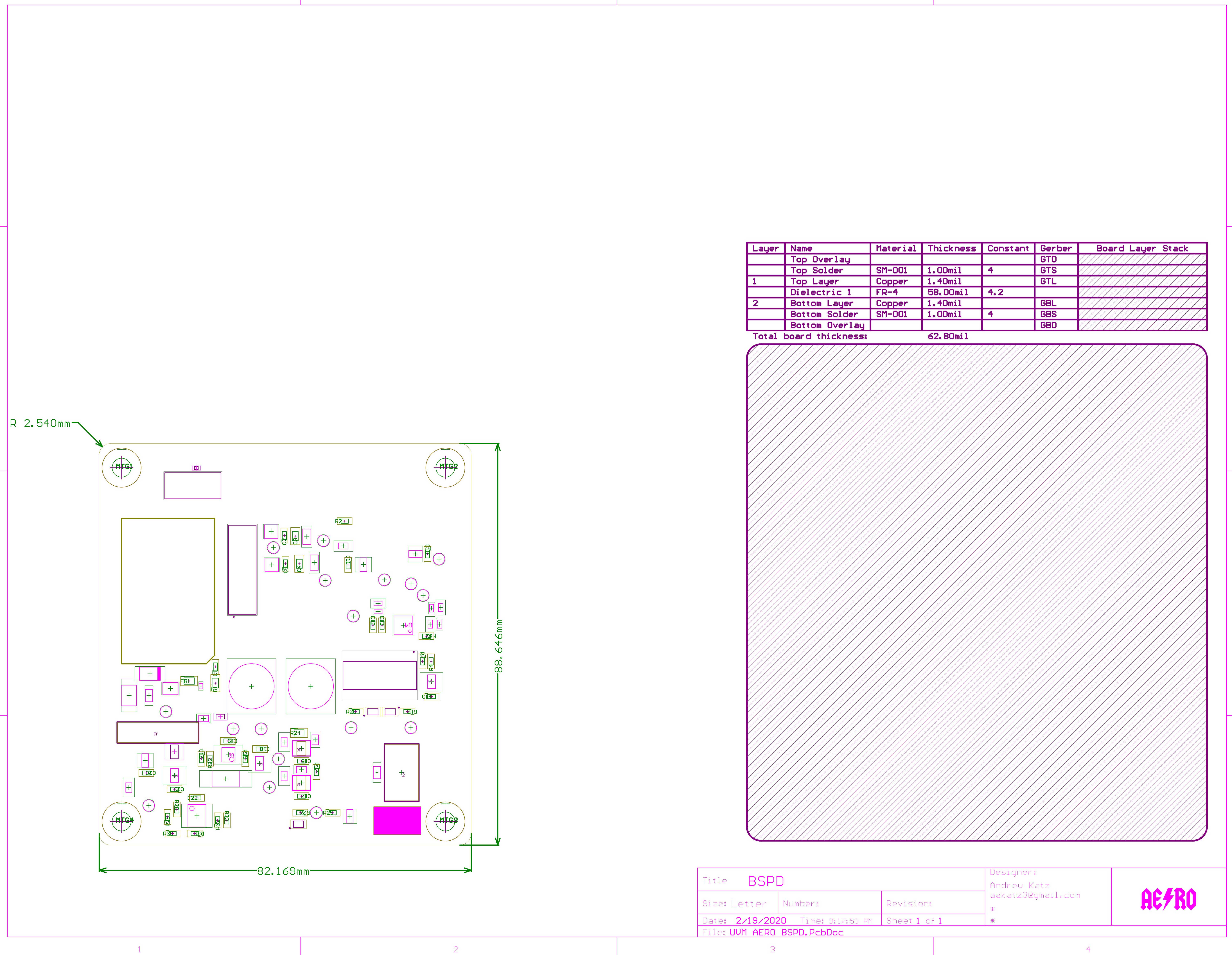


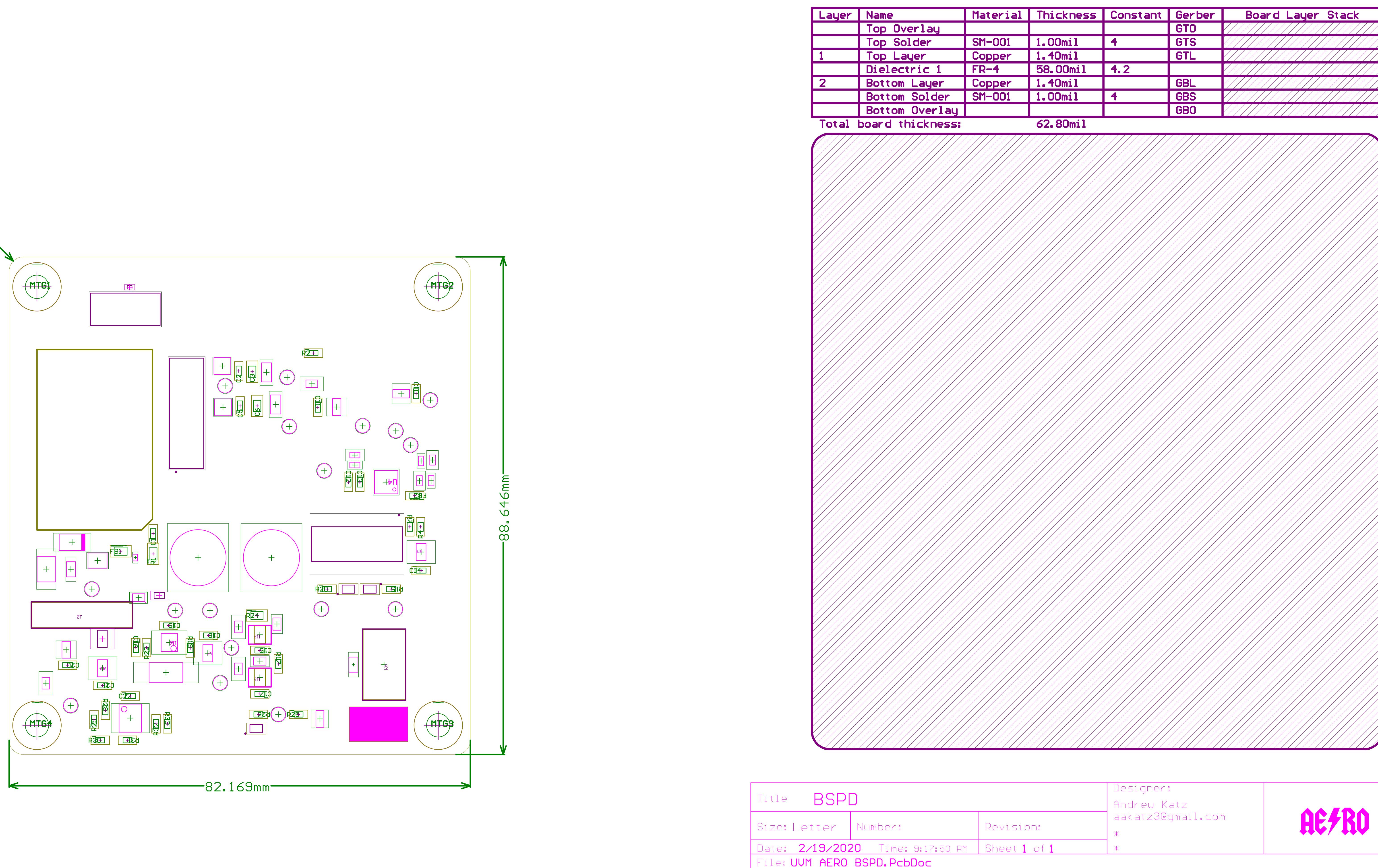


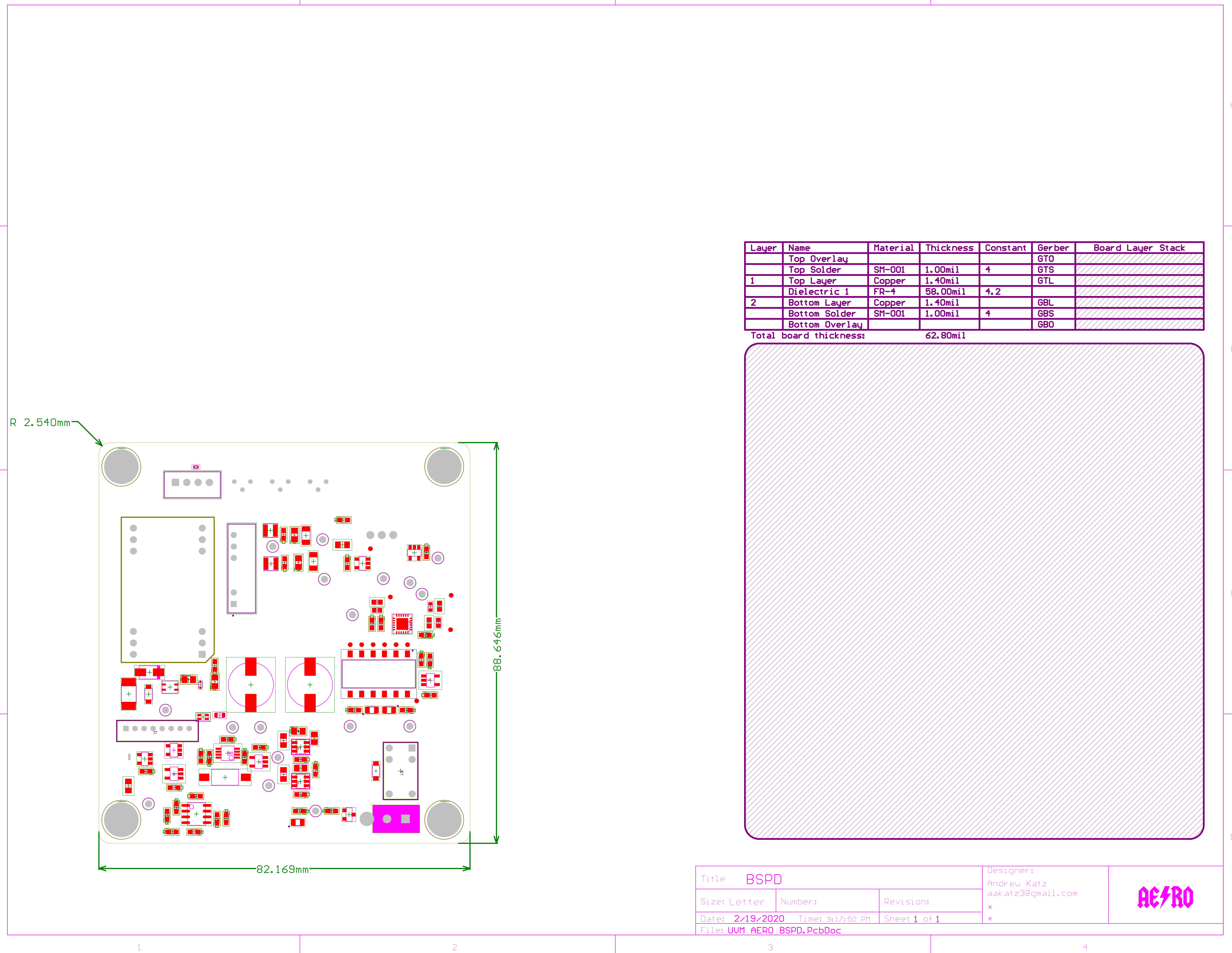


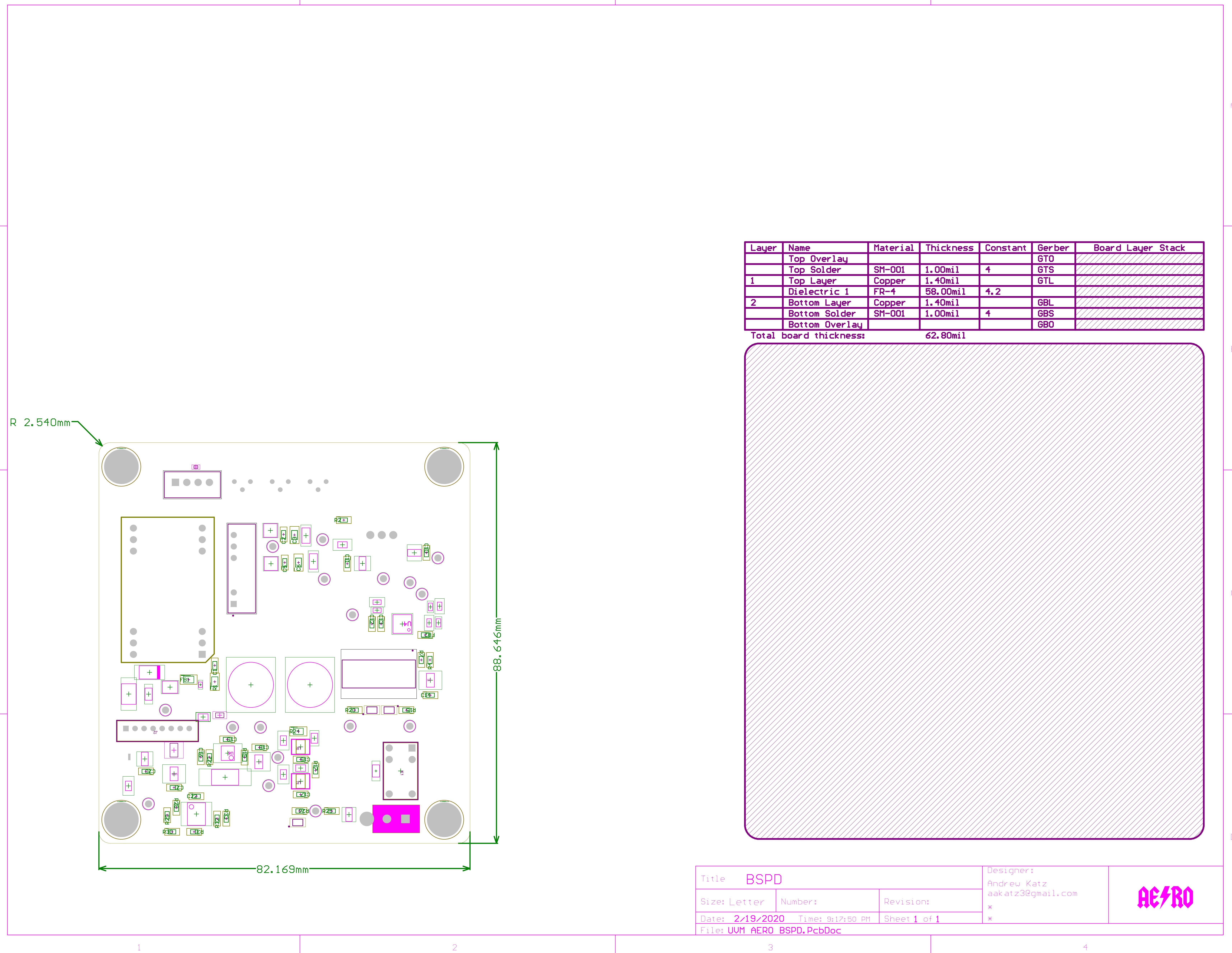


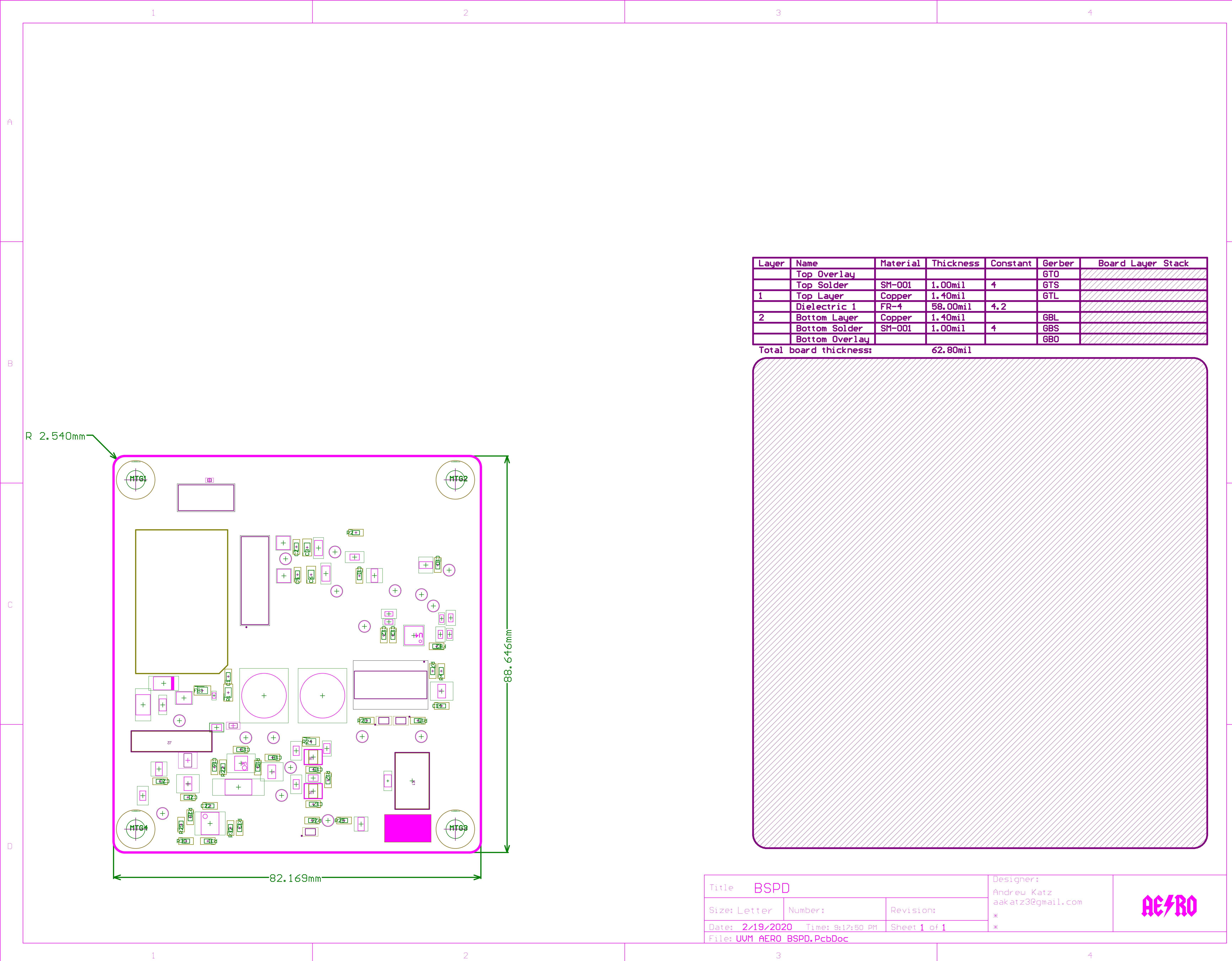








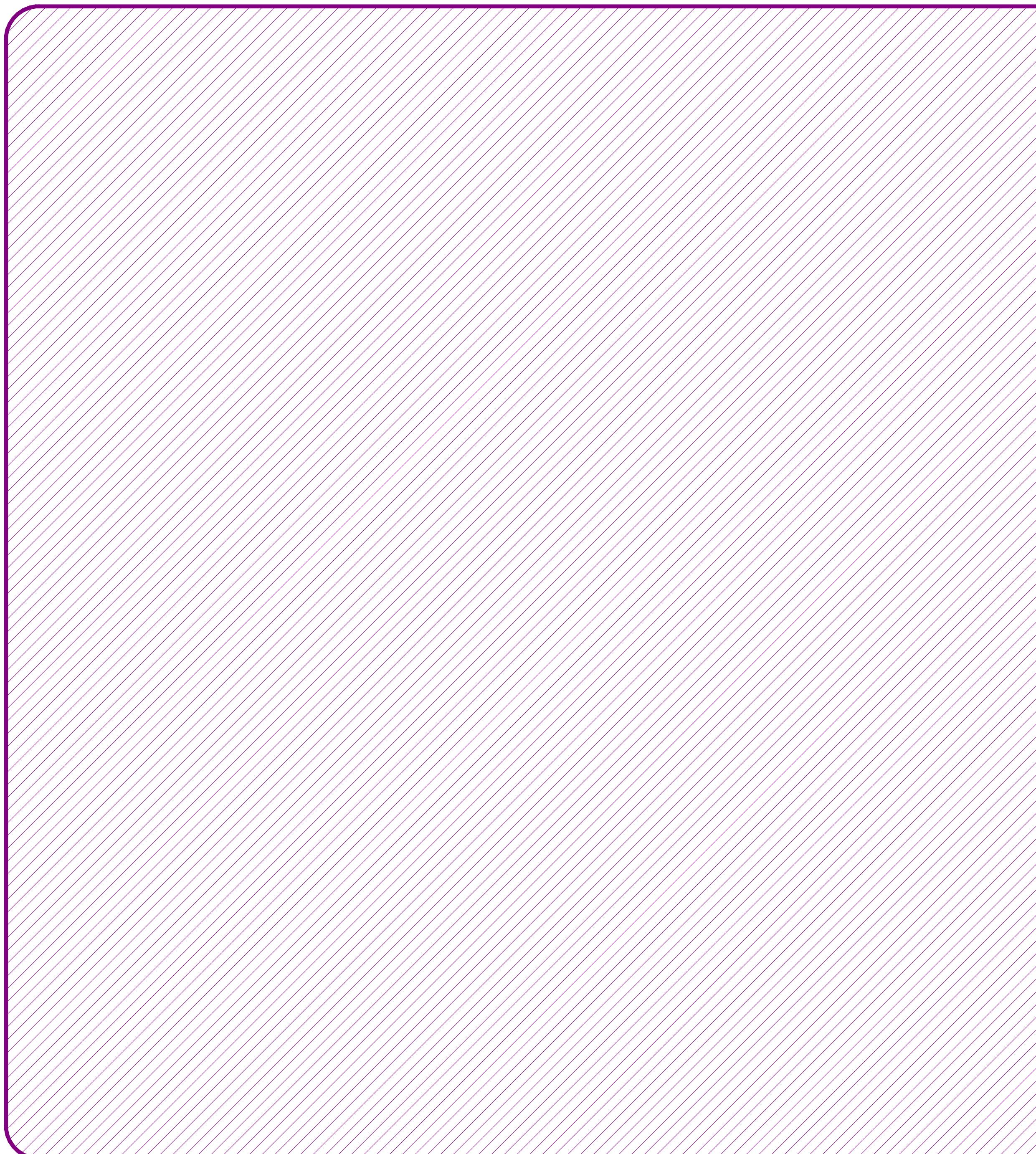
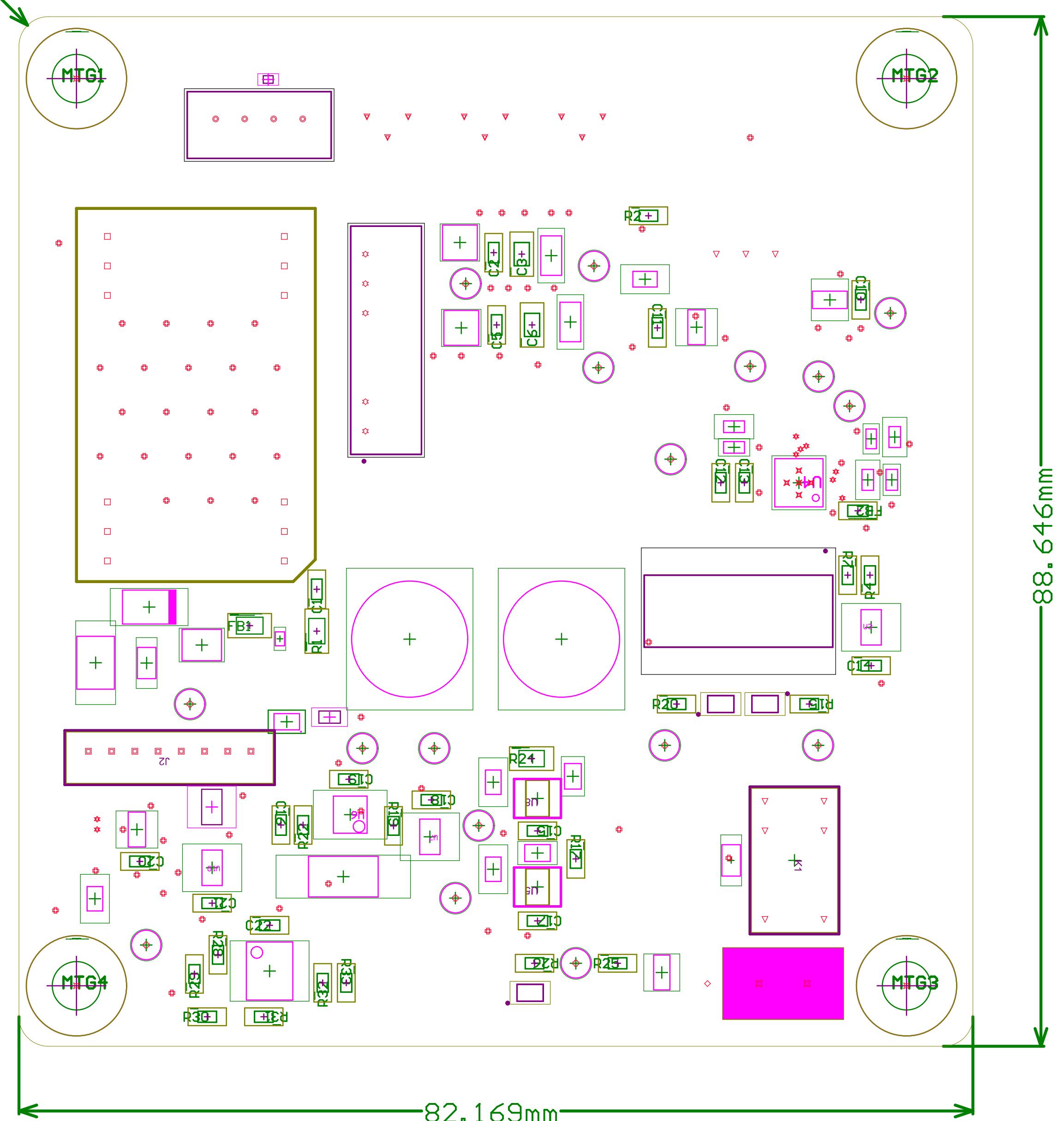




Symbol	Count	Hole Size	Plated	Hole Type	Via/Pad	Pad Shape	Template
◊	1	125.00mil (3.175mm)	NPTH	Round	Pad	Rounded	c318hn318m0mx0
☒	2	55.00mil (1.397mm)	PTH	Round	Pad	(Mixed)	(Mixed)
◎	4	41.73mil (1.060mm)	PTH	Round	Pad	(Mixed)	(Mixed)
☒	4	142.00mil (3.607mm)	PTH	Round	Pad	Rounded	c762h361
☒	5	7.87mil (0.200mm)	PTH	Round	Via	Rounded	v50h20
☒	5	32.28mil (0.820mm)	PTH	Round	Pad	(Mixed)	(Mixed)
☒	8	27.56mil (0.700mm)	PTH	Round	Pad	(Mixed)	(Mixed)
☒	9	9.00mil (0.229mm)	PTH	Round	(Mixed)	(Mixed)	(Mixed)
▽	9	20.00mil (0.508mm)	PTH	Round	Pad	Rounded	c102h51p25502
▽	9	39.37mil (1.000mm)	PTH	Round	Pad	(Mixed)	(Mixed)
□	12	30.00mil (0.762mm)	PTH	Round	Pad	(Mixed)	(Mixed)
▢	17	40.00mil (1.016mm)	PTH	Round	Pad	Rounded	c155h102
▢	79	15.00mil (0.381mm)	PTH	Round	Via	Rounded	v76h38
164 Total							

Layer	Name	Material	Thickness	Constant	Gerber	Board Layer Stack
	Top Overlay				GTO	
	Top Solder	SM-001	1.00mil	4	GTS	
1	Top Layer	Copper	1.40mil		GTL	
	Dielectric 1	FR-4	58.00mil	4.2		
2	Bottom Layer	Copper	1.40mil		GBL	
	Bottom Solder	SM-001	1.00mil	4	GBS	
	Bottom Overlay				GOB	

Total board thickness: 62.80mil



Title: BSPD	Designer: Andreu Katz aakatz3@gmail.com
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